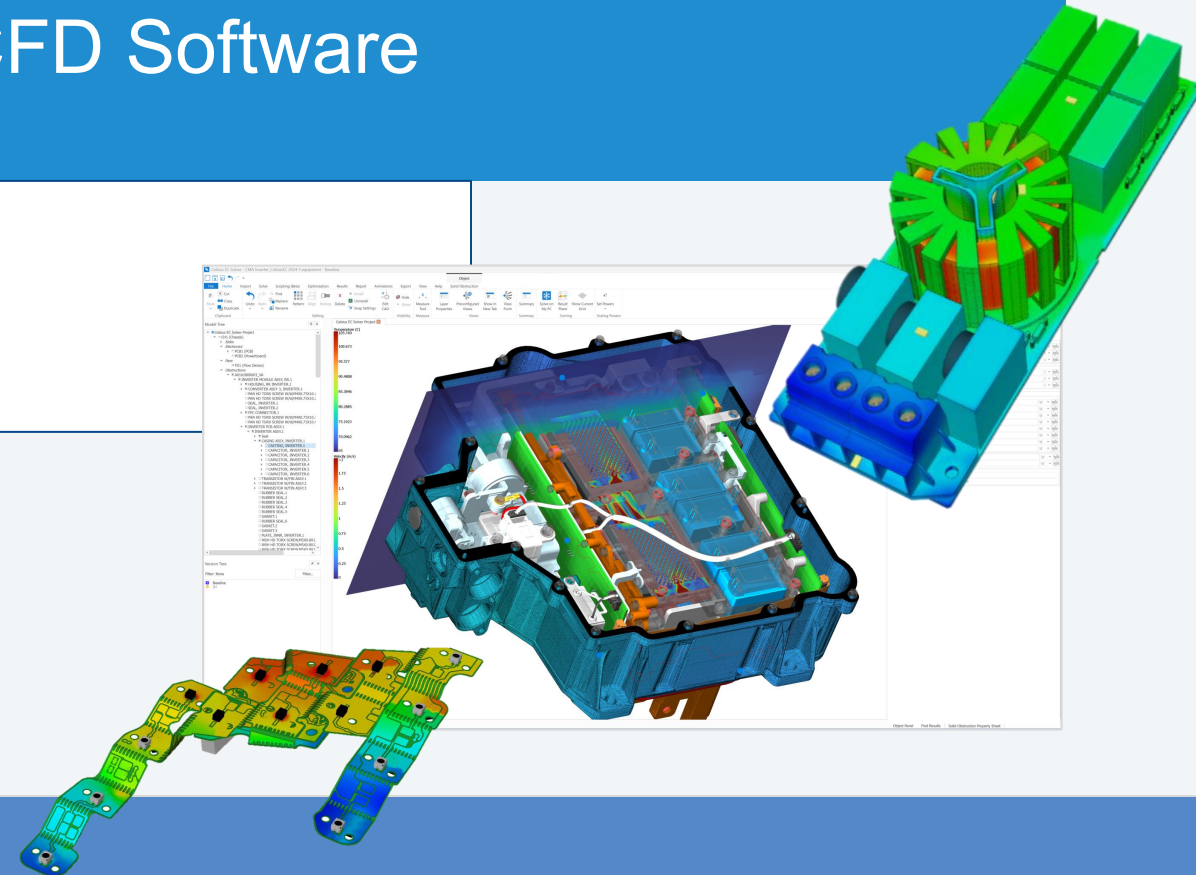
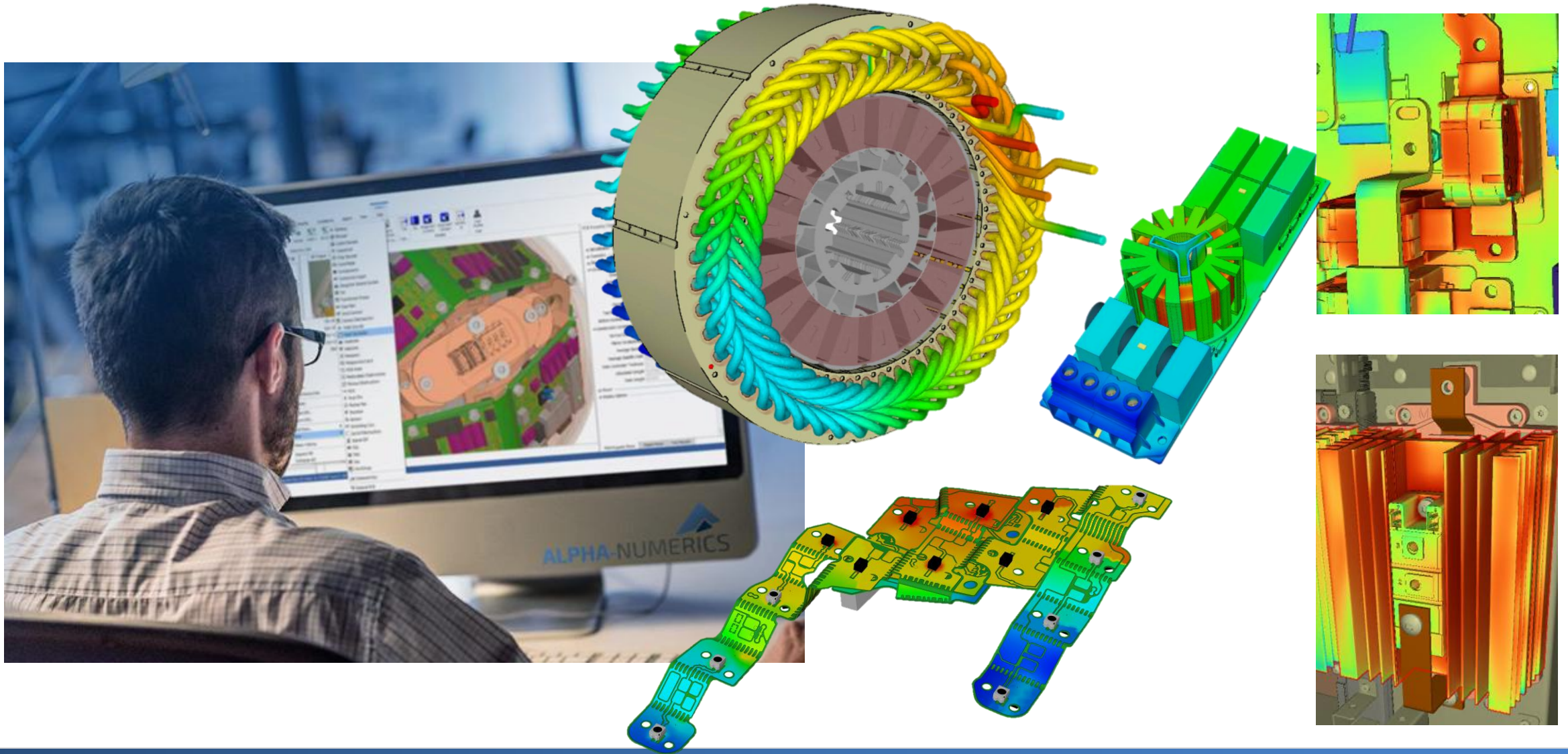


Welcome

CelsiusEC, an Industry Specific CFD Software

Tobias Best, ALPHA-Numerics GmbH







Engineering Office near Wiesbaden

Specialist for Electronics Cooling

Simulation Service & Consulting

EC trainer / SW trainer

Cadence Software Reseller

Hotline & Technical Support

A Mentor for CelsiusEC Starters

We have been working with the electronics industry in the field of electronics cooling for 30 years.
We support our customers to develop innovative cooling solutions for their electronic equipment.

Mercedes	Brose	Elektrobit
TE	Rexroth	Kostal
OSRAM	HILTI	Vishay
SE	PREH	Joynext
Rohde & Schwarz	Diehl Aerospace	Phoenix Contact
FESTO	Compleo	Magna
Borg Warner	Porsche	Sick
And many more	Schölly	Siedle





WEBINAR

Practical Guide to Electronics Cooling with Cadence Celsius EC

REGISTER NOW

- Optimize Airflow**
Improve cooling performance
- Reduce Hotspots**
Enhance reliability and longevity
- Design with Confidence**
Simulate early and validate faster

Practical Guide to Electronics Cooling Design with Cadence Celsius EC

Date: June 23, 2026

Time: 2 PM ET | 11 AM PT or 11AM CEST

Presenter: Tobias Best, General Manager ALPHA-Numerics GmbH

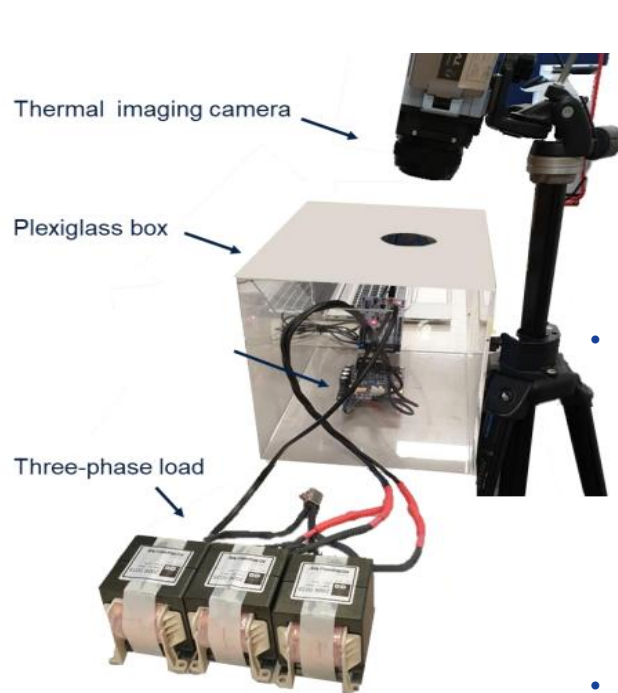
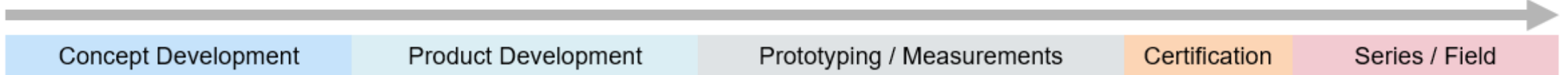
Key Takeaways

By the end of this webinar, you will:

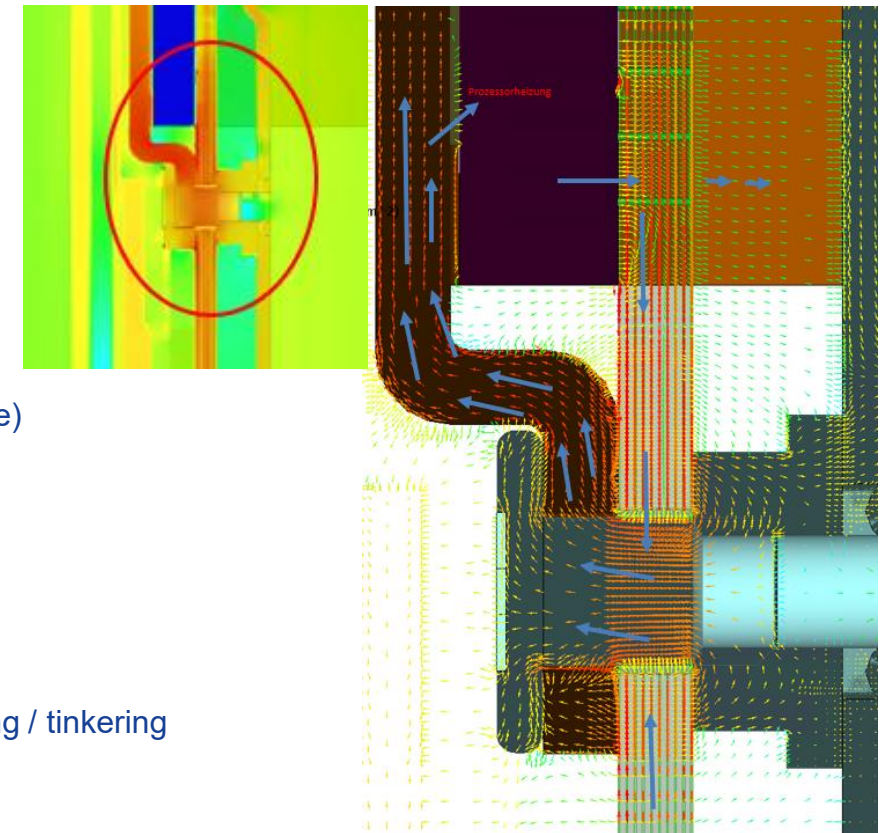
- Understand how to use Celsius EC to model real-world electronics cooling scenarios with confidence
- Be able to set up and execute a complete thermal simulation workflow from setup through results
- Gain practical tips to improve model fidelity while reducing setup time
- Learn how to identify thermal risks earlier and optimize cooling strategies before hardware is built
- Walk away with a repeatable approach for integrating thermal analysis into your design process

When and Why to shift left from physical testings to simulation

Product development timeline

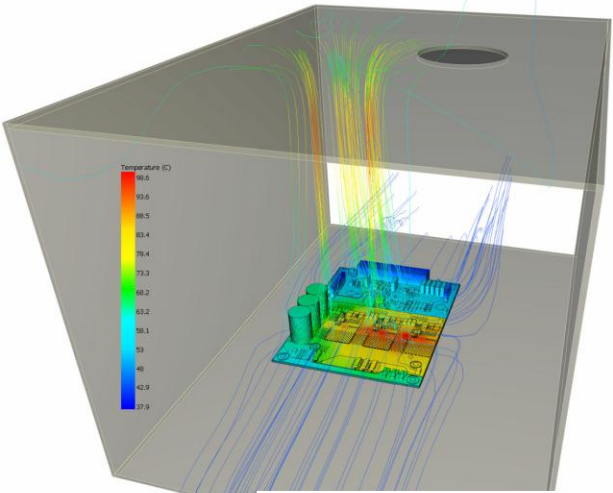
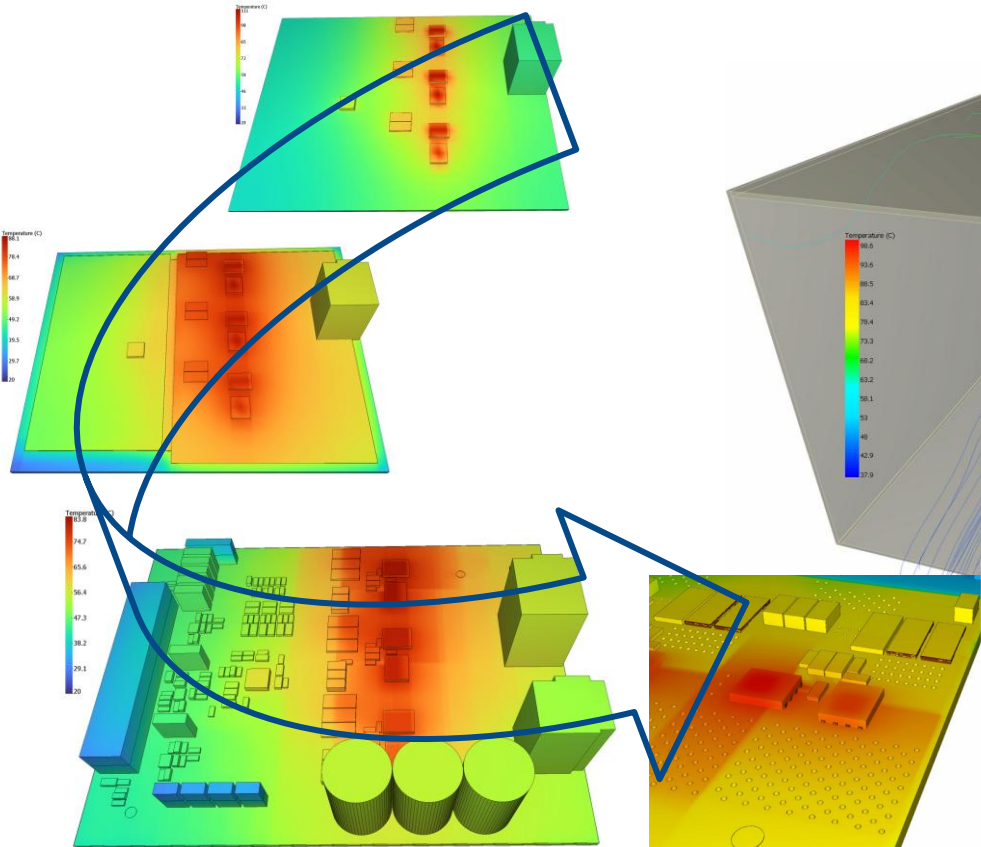


- Later understanding of the thermal behaviour and thus
 - Expensive troubleshooting
 - Delay in market launch (competitive disadvantage)
 - Expensive solutions
 - oversized?
 - heavy
 - puts the brakes on innovation
 - makes it complicated?
- Measurements are selective
 - No information about thermal paths.....blind poking / tinkering
 - No certainty of having caught the hotspot

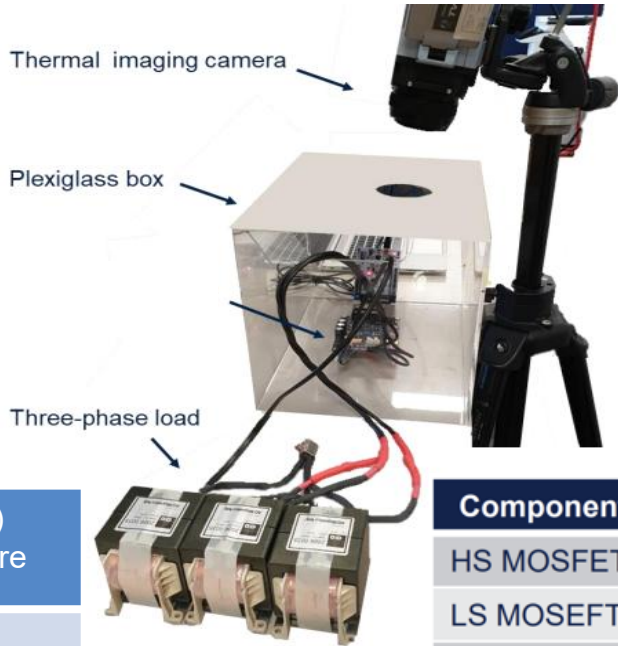


When and Why to shift left from physical testings to simulation

Product development timeline



Simulation Results (°C) at 25.8°C lab temperature	
	93.5
	91.1
	82.4

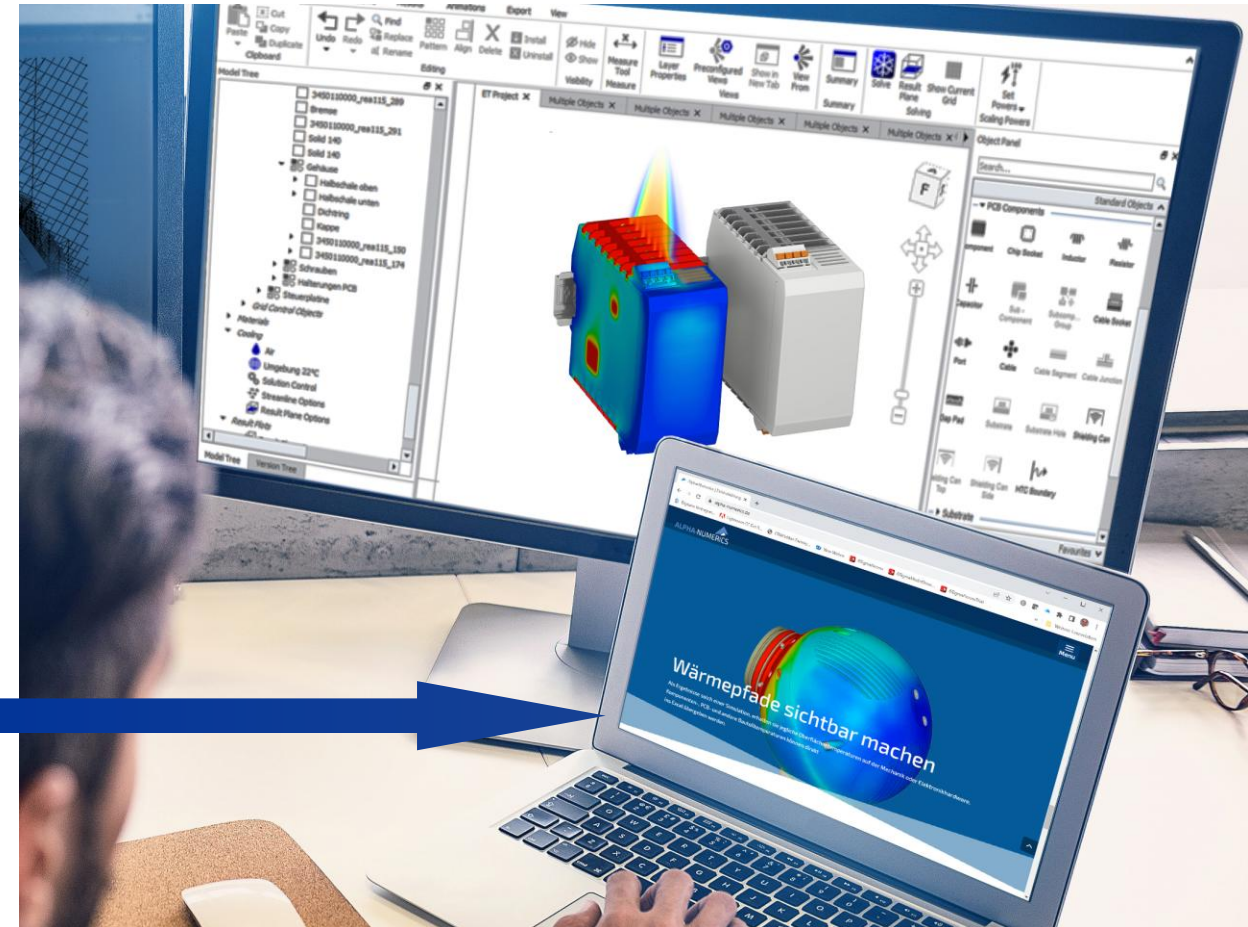
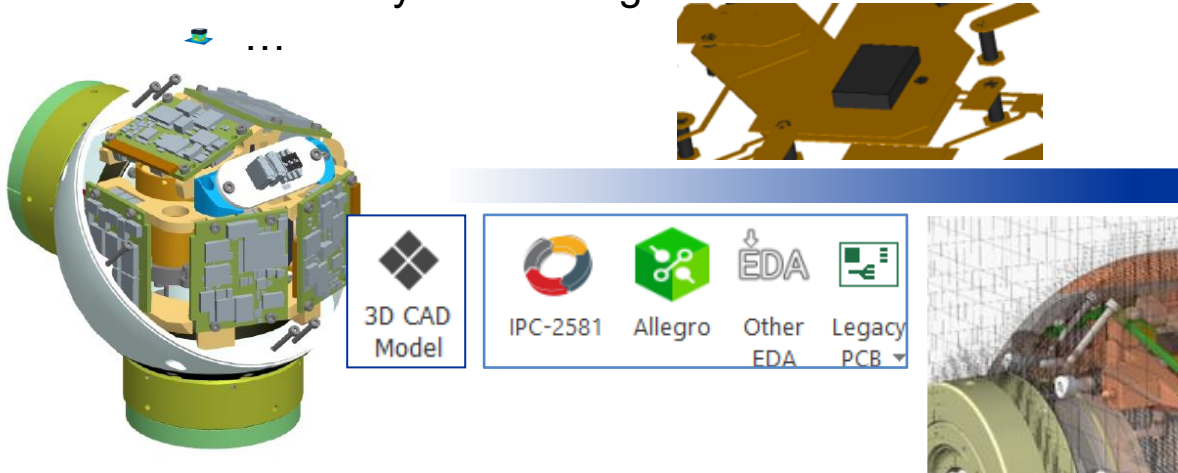


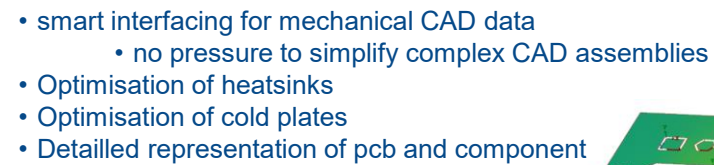
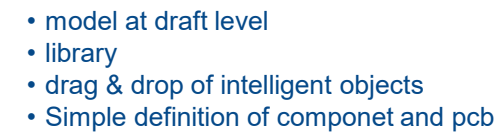
Component	Measure [°C]
HS MOSFET Q1	93.8
LS MOSEFT Q4	91.7
Shunt resistor R23	82.6

Let's start introducing you into CelsiusEC

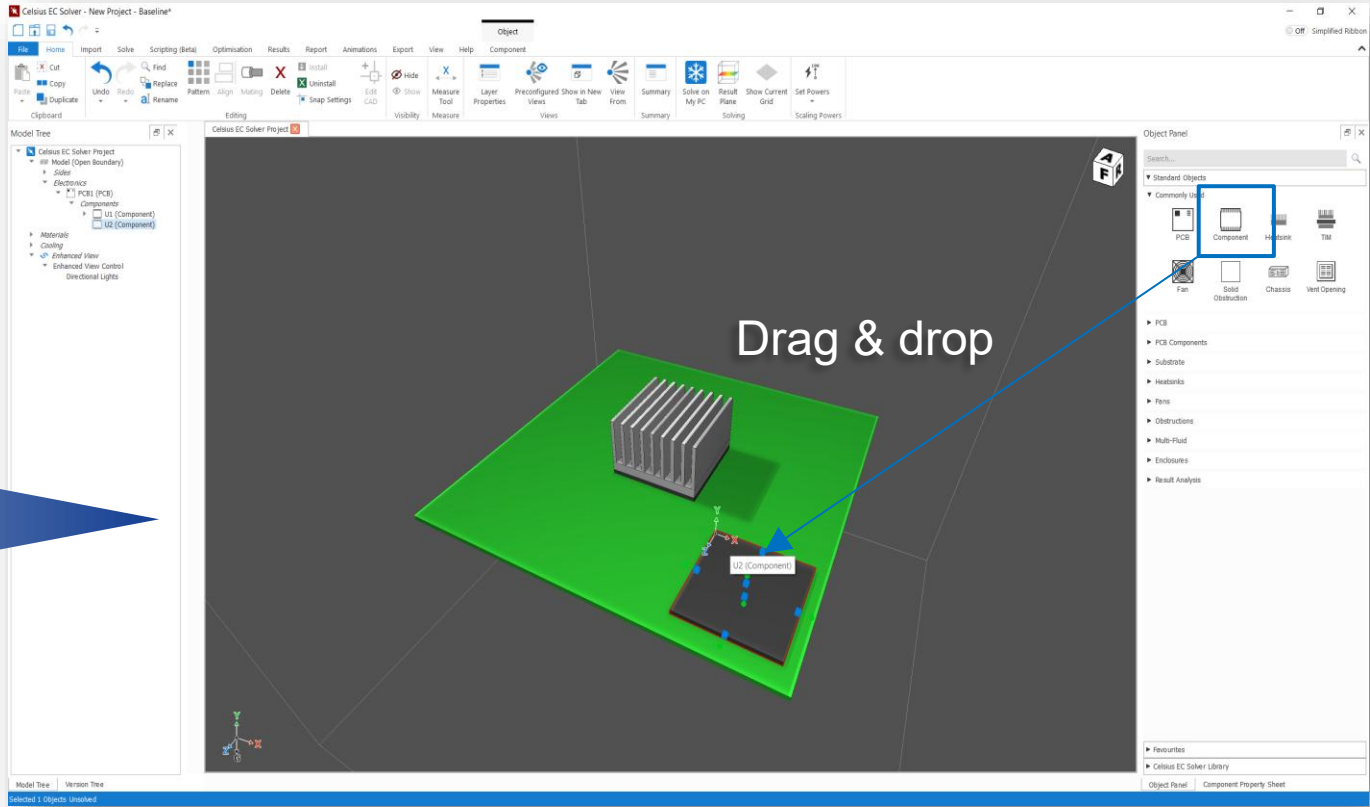
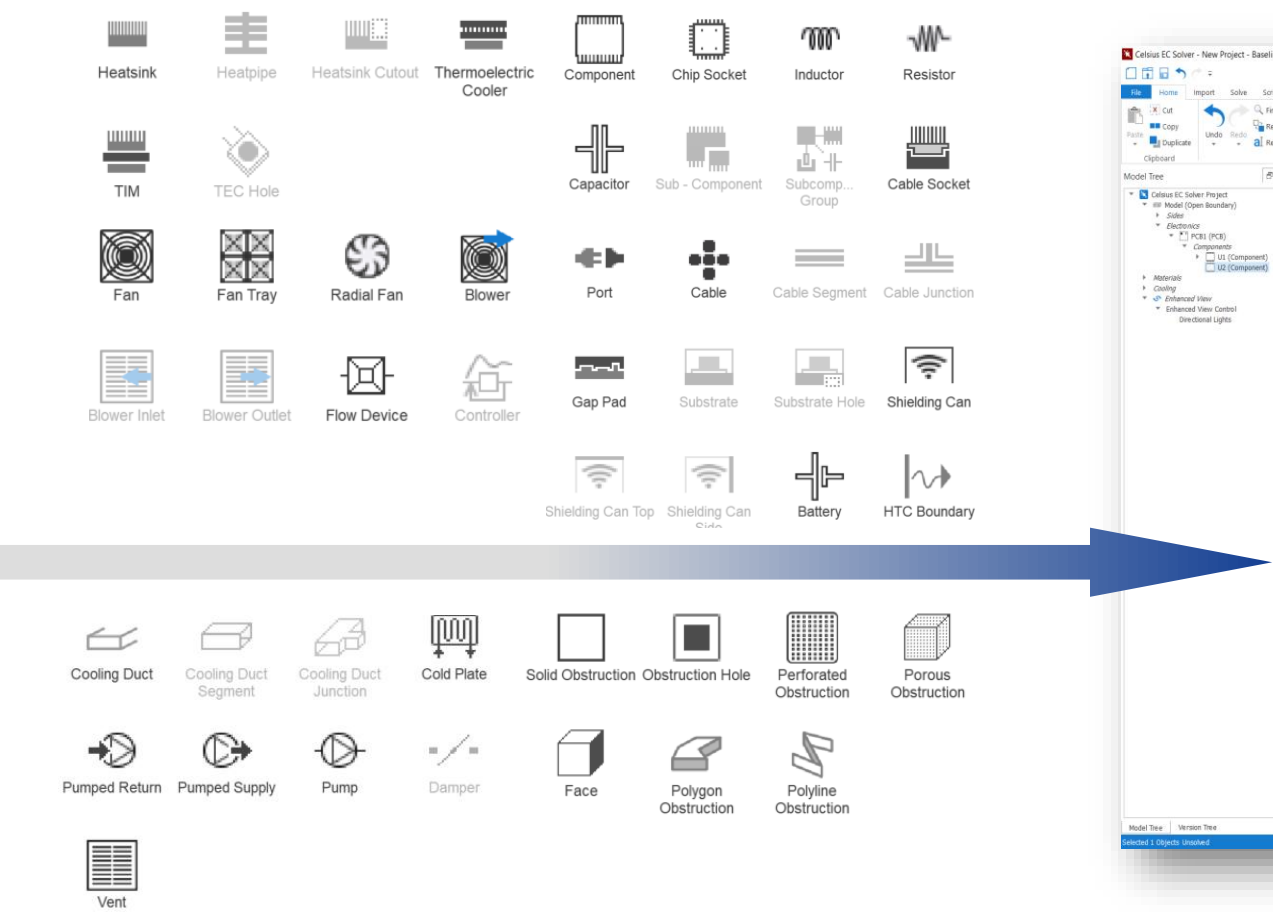
CelsiusEC is an Industry specific CFD Software

- GUI is easy to use for Engineers
 - Mechanical Engineers
 - Hardware Engineers
 - Testing / Measurement Specialists
- Task related Objects
- Import Filters of all relevant Datasets
- Supporting Automatism
 - Modelling
 - Meshing
 - Physical Settings

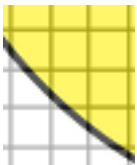
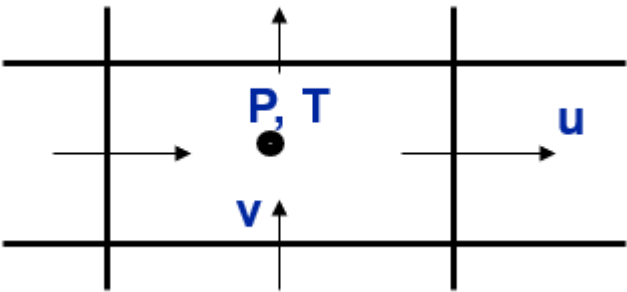
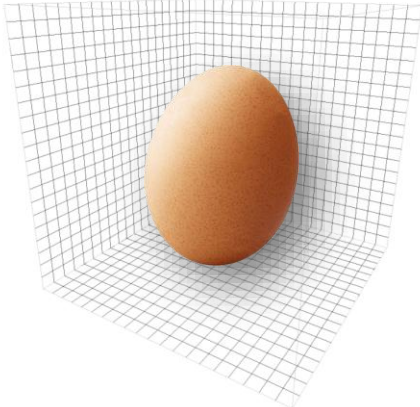
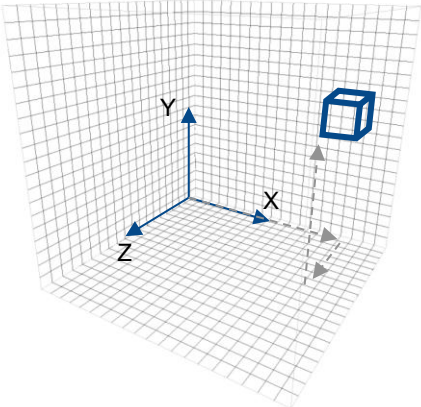
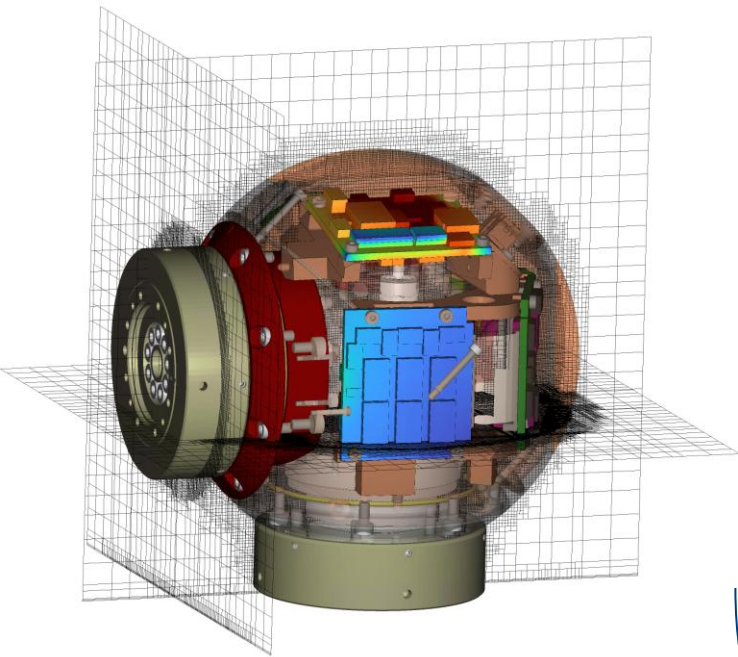




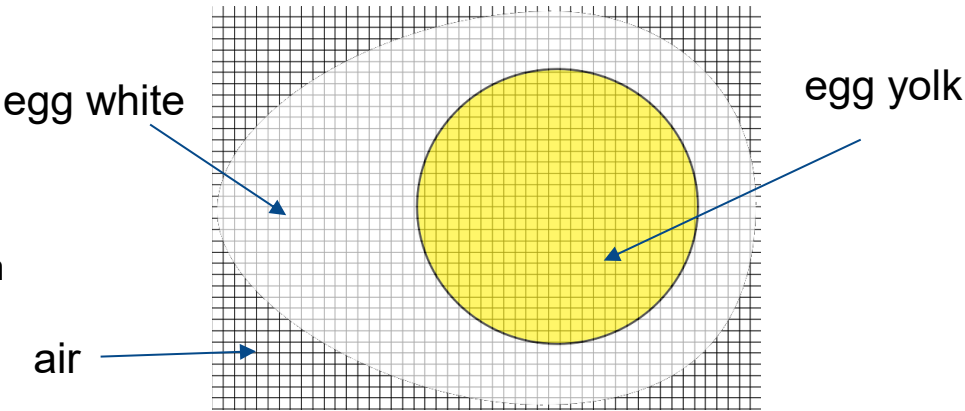
From Concept Level to a Digital Twin



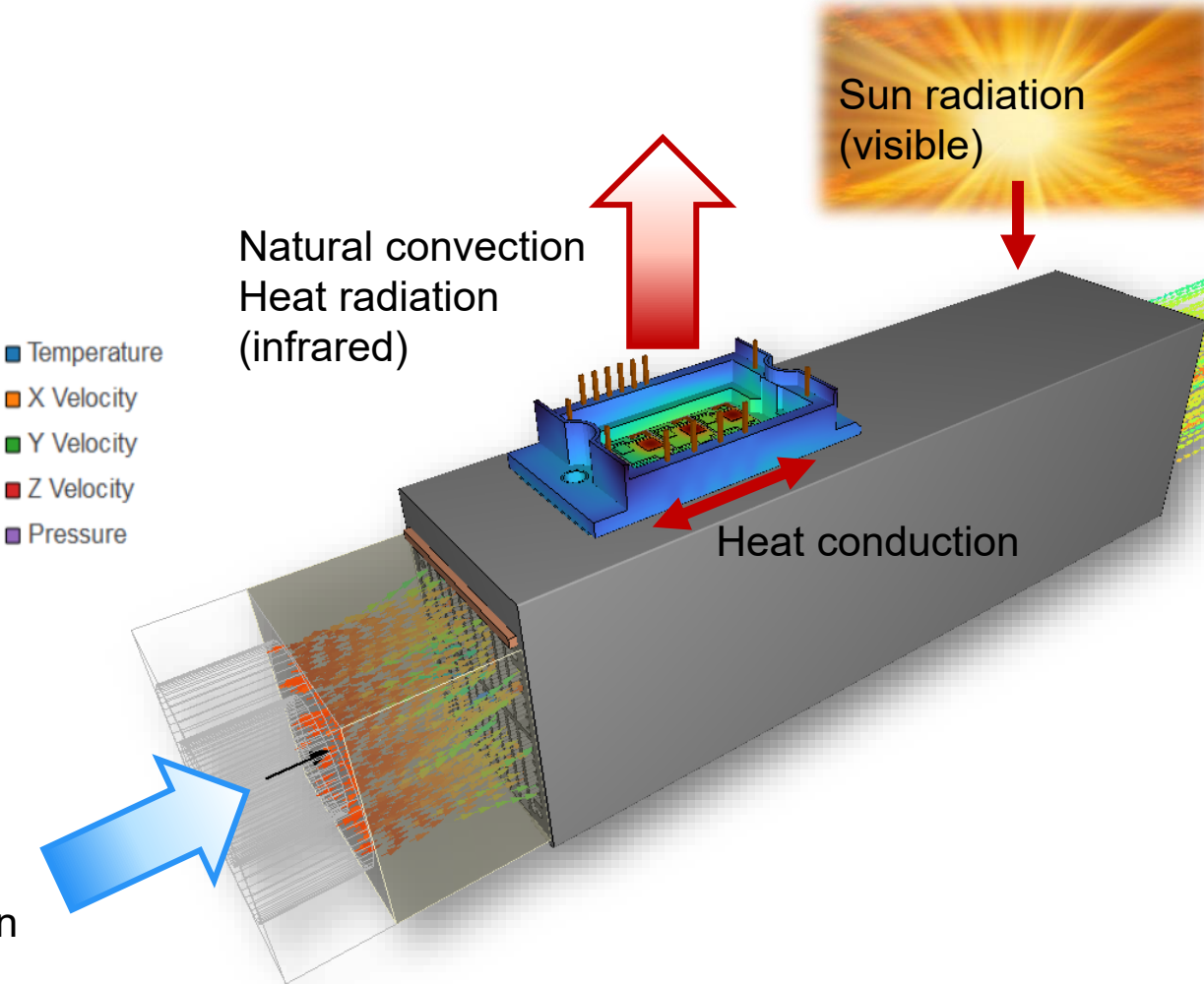
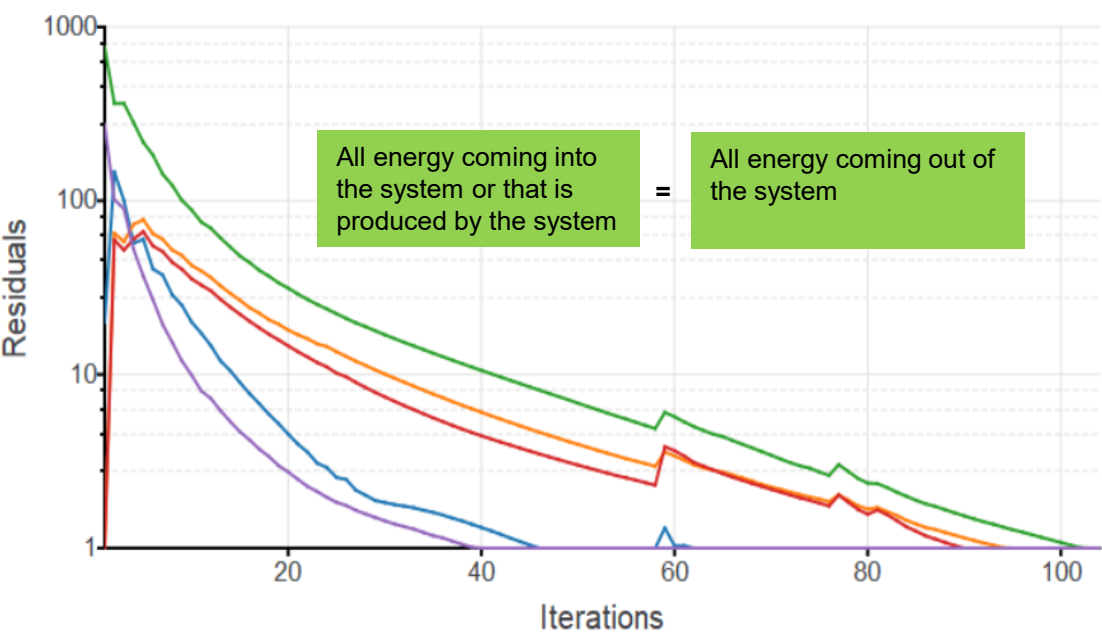
Meshing – it is not very complex

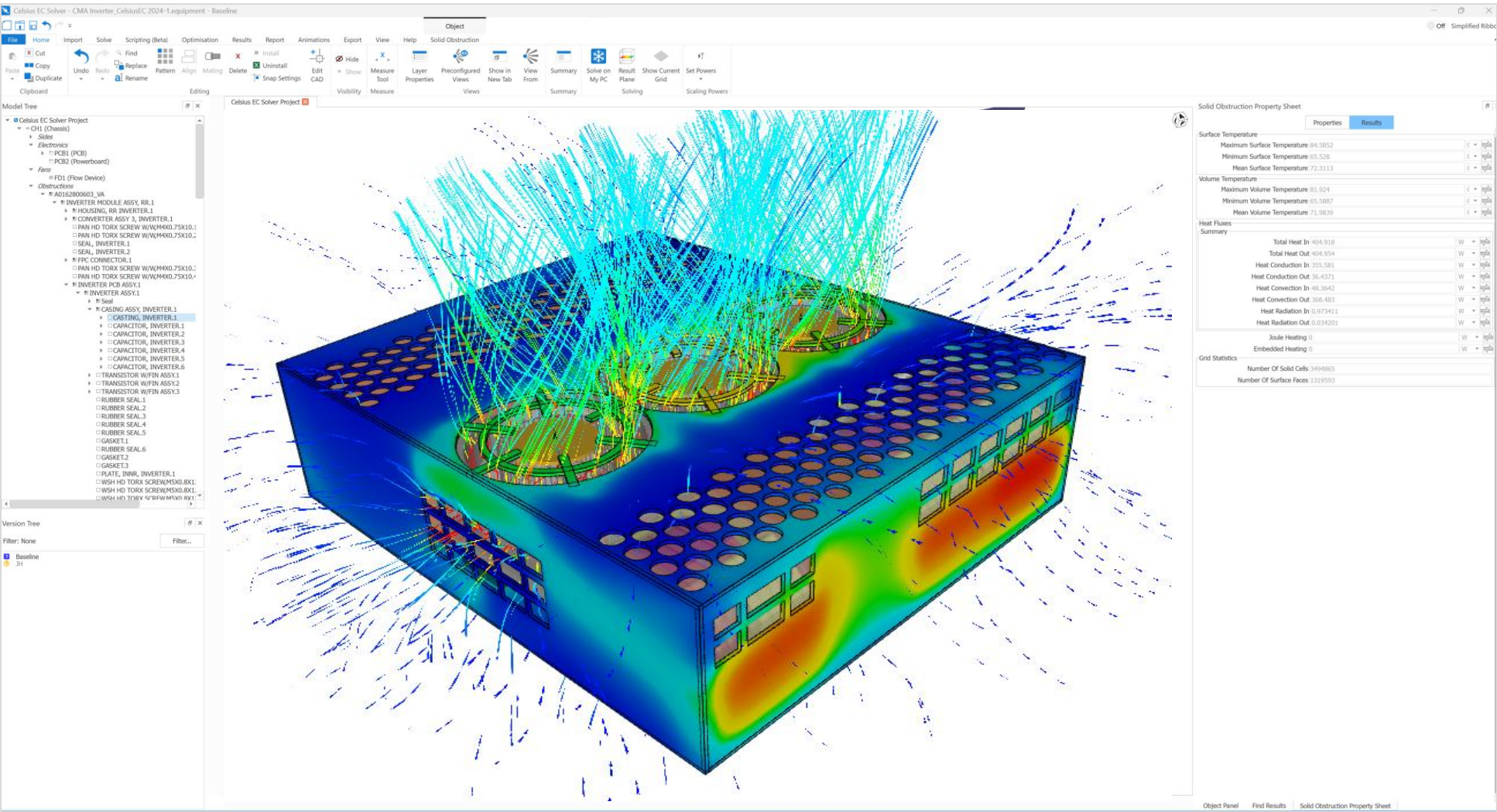


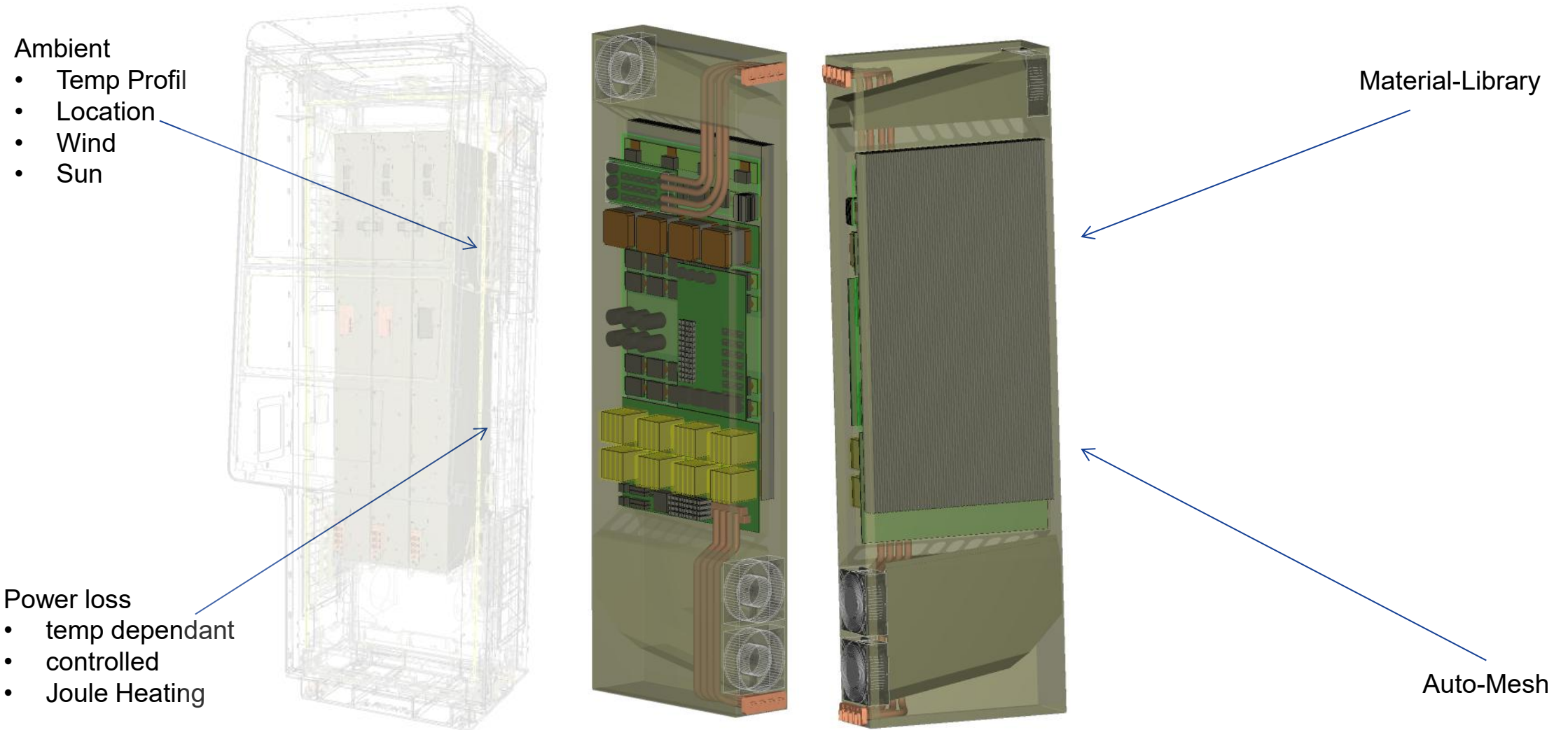
- Position
- Material
- Surface classification



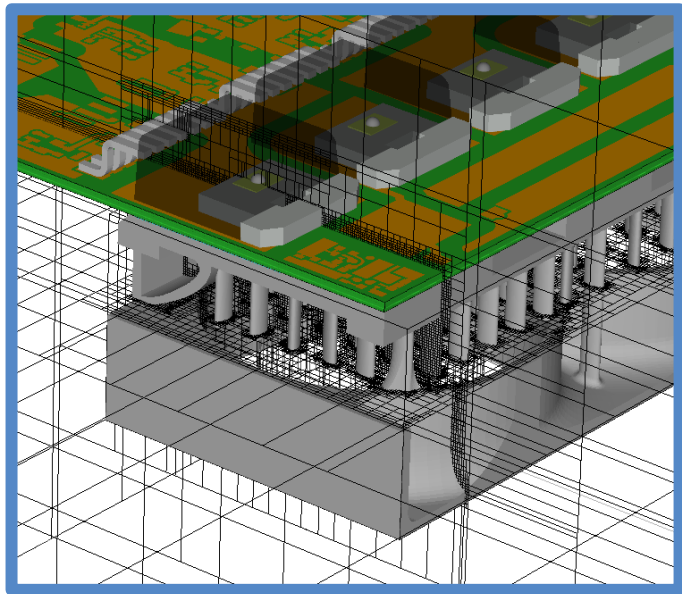
CFD Solution Residuals







Meshing – it is not very complex



▼ Hybrid Cells

Allow ☒

Exclude Flow Boundaries ☐

▼ Grid

Unstructured Grid Control

Limit Refinement Ratio ☒

Refinement Ratio Limit 2

Gap Refinement ☐

Grid Plane Display

X Location 0 mm

Y Location 0 mm

Z Location 0 mm

Grid Rules Definition File GridRules.cfg

Limit Maximum Cell Size

Cell Count Target 50000000

Minimum Gap Size 0.5 mm

Enable Heat Conduction Gri... ☒

Use Advanced Grid Controls ☒

Allow Manual Only Gridding ☐

Use Inflation ☒

Apply Smoothing ☐

Mounting Rail Simplification ☐

Grid Summary

Grid Cell Count no value

Auto (Unlimited) Cell Count no value

Largest Cells

Largest X no value

Largest Y no value

Largest Z no value

Smallest Cells

Smallest X no value

Smallest Y no value

Smallest Z no value

Maximum Aspect Ratio no value

Maximum Expansion Ratio no value

Maximum Refinement Ratio no value

☐ CAD Object xyz

☒ Grid Control 3D 3x3x3mm

☒ Grid Control GEO based

Grid Rule handled as a 3D Object

Installed ☒

► Identification

▼ Geometry

Direction X

Size From Parent X

► Construction

► Display Options

3D Geometry Based

X Construction

Extra Grid Type Maximum Size

Maximum Size 3 mm

Exact Grid Lines ☐

Y Construction

Extra Grid Type Maximum Size

Maximum Size 3 mm

Exact Grid Lines ☐

Z Construction

Extra Grid Type Maximum Size

Maximum Size 3 mm

Exact Grid Lines ☐

▼ Construction

Geometry Based Construction

Apply To Solid ☒

Maximum Size In Solid 1 mm

Apply To Fluid ☐

Inflate Into Fluid ☒

Inflation Settings

Apply To Inside Fluid ☒

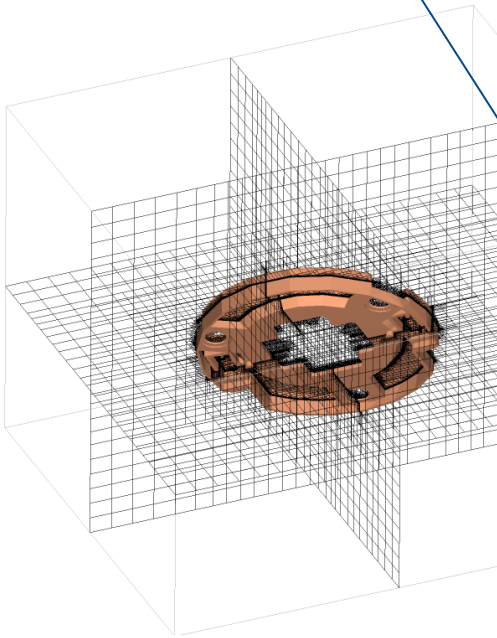
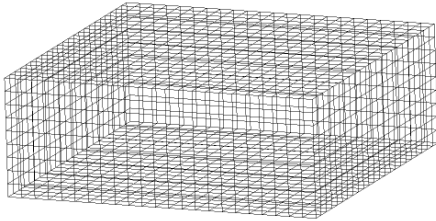
Maximum Size In Inside Fluid 0.2 mm

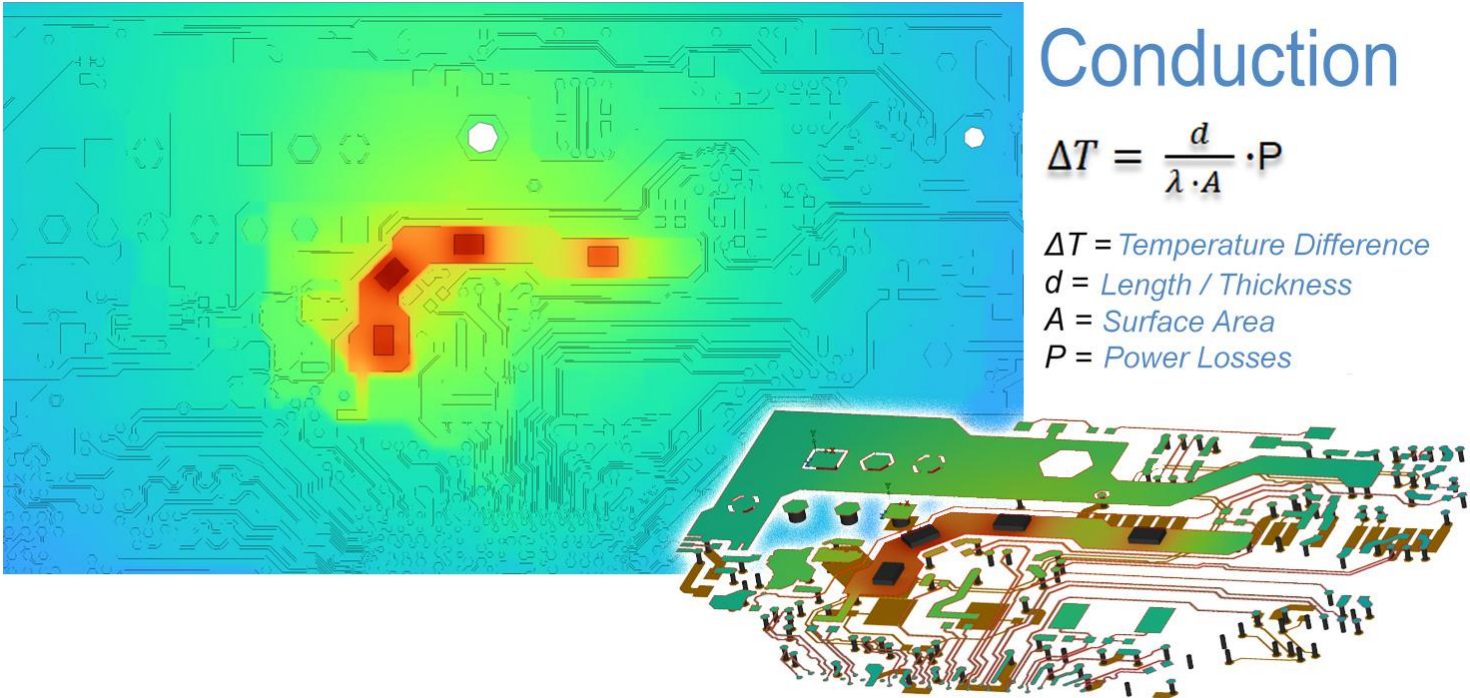
Extent In Inside Fluid 0.4 mm

Apply To Outside Fluid ☒

Maximum Size In Outside Fluid 0.2 mm

Extent In Outside Fluid 0.4 mm





Conduction

$$\Delta T = \frac{d}{\lambda \cdot A} \cdot P$$

ΔT = Temperature Difference
 d = Length / Thickness
 A = Surface Area
 P = Power Losses

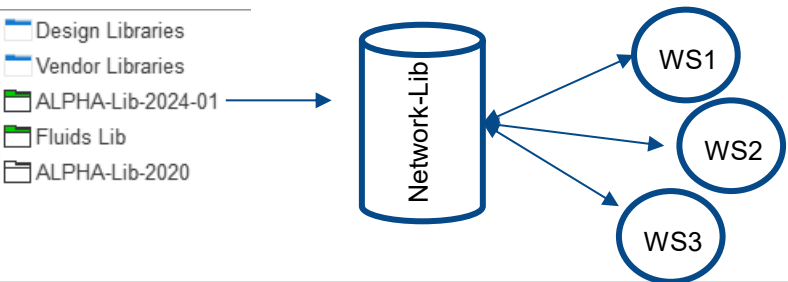
- Conduction-Only Calculation possible (Vaccum)
- Isotropic -> Temperature Dependent
- Plana Isotropic (Flex-PCB)
- Orthotropic
- Radial Conducting (Battery Cells)
- Thermal & Electrical Contact Resistance

A 3D model of a mechanical assembly, possibly a heat exchanger or a component with thermal contacts. It shows a green base with a central red/orange component. A blue arrow points to a specific part of the assembly.

▼ Construction

Thermal Specification	Resistance	
Solid-Solid Resistance	0.02	C/W
Solid-Fluid Resistance	0.02	C/W
Electrical Resistance	0	Ohm
Surface Emissivity	1	

Local & Central Library Structure for Materials (...and other Objects)

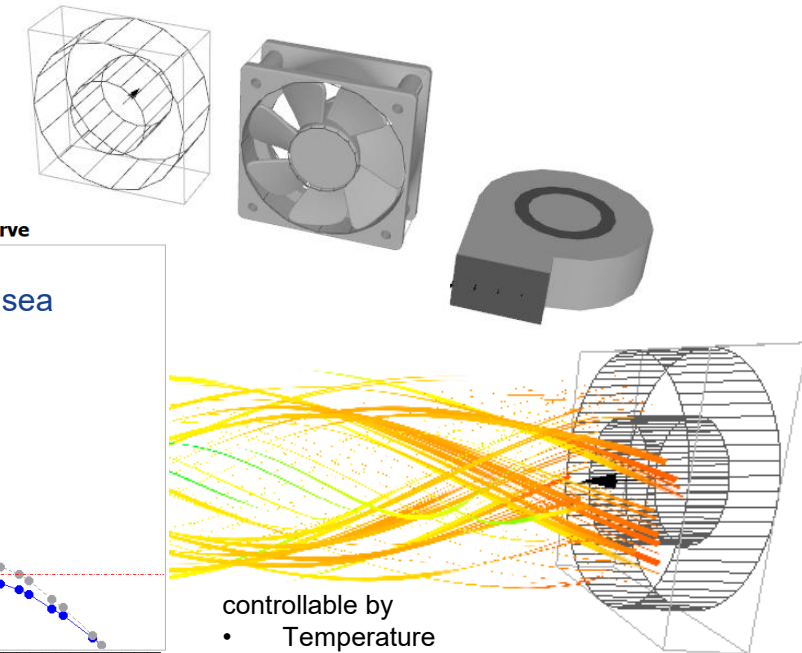
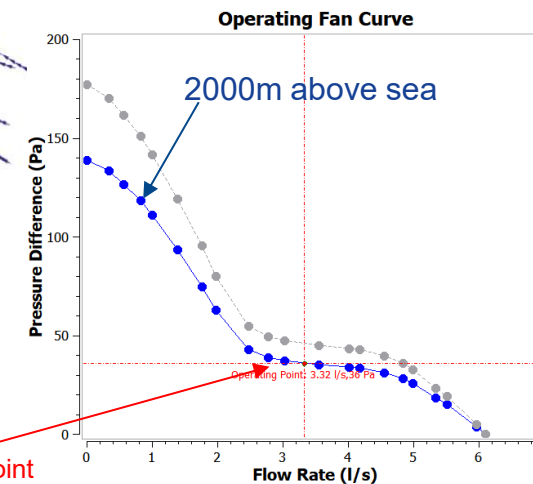
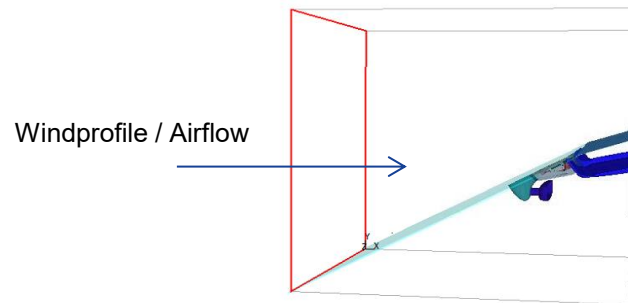
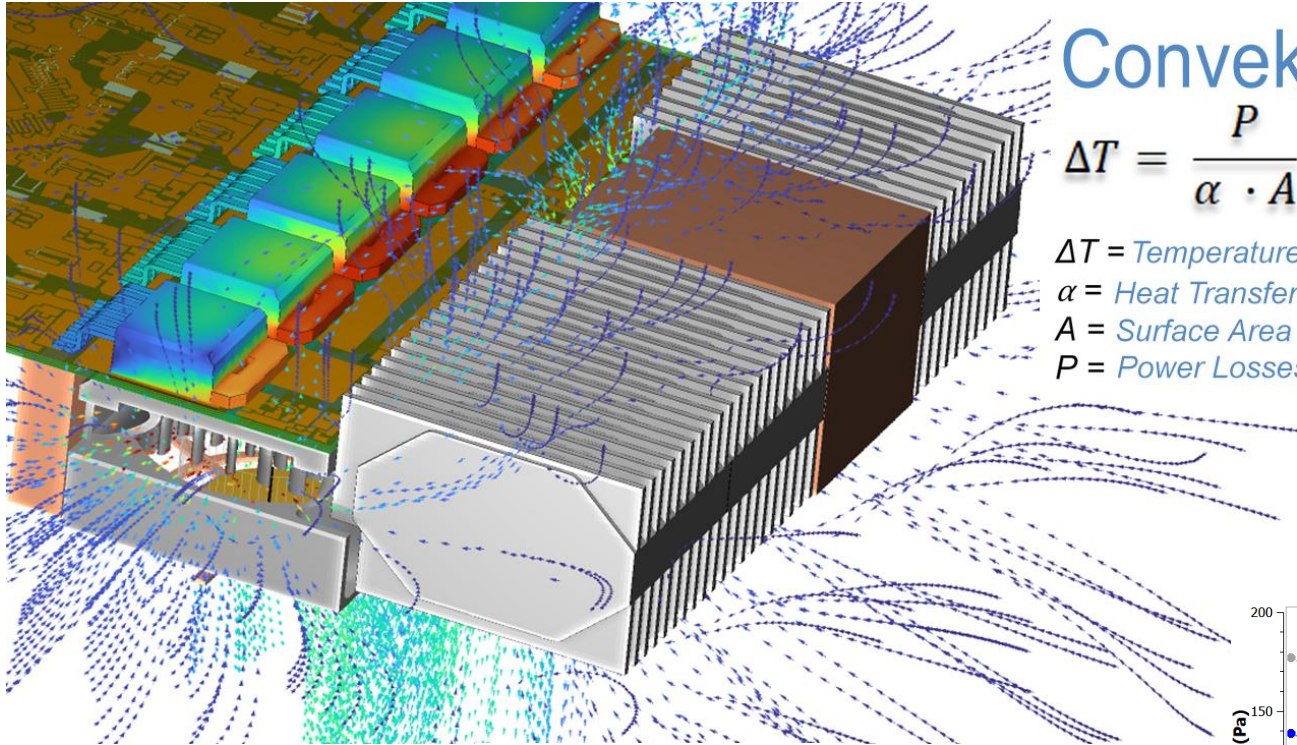


Convektion

$$\Delta T = \frac{P}{\alpha \cdot A}$$

ΔT = Temperature Difference
 α = Heat Transfer Coefficient
 A = Surface Area
 P = Power Losses

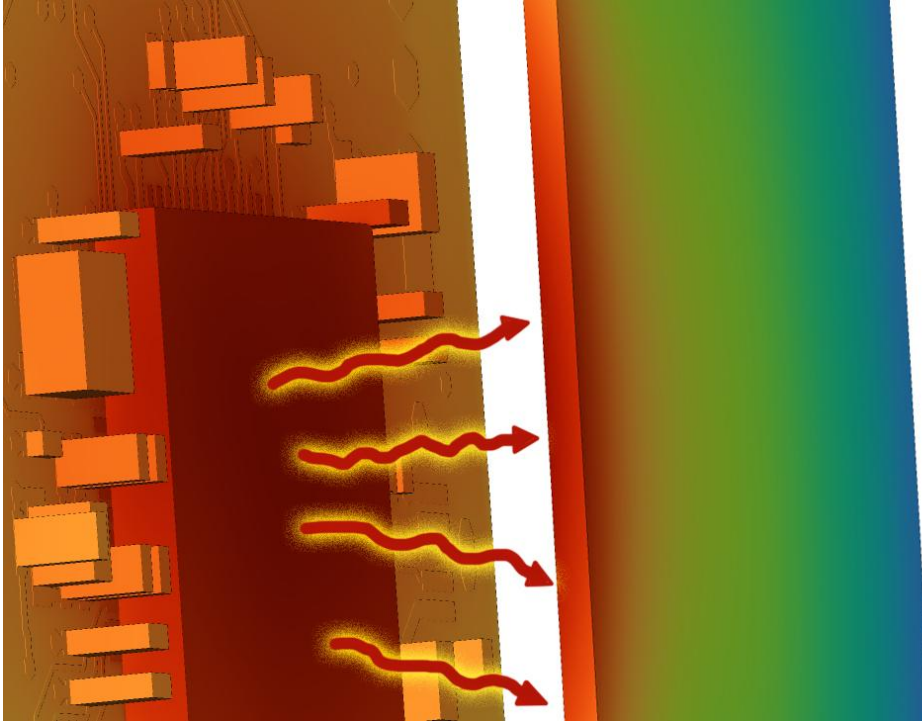
- Flow-Only Calculation possible
- Free Convection
- Forced Convection (KE Solver)
 - Flexible Wallfunctions
- Calculated at any local cell at surfaces the right HTC
 - Defined Heat Transfer Coefficient possible
- MultiFluid Calculation (no Phase Change!)



controllable by

- Temperature
- RPM

Operation Point



Radiation

$$\dot{Q} = \frac{\partial Q}{\partial t} = \epsilon \sigma A T^4$$

$\dot{Q}$: Radiation Heat Fluxes

ϵ : Emissivity

$$\sigma = 5,67 \cdot 10^{-8} \frac{\text{W}}{\text{m}^2 \text{K}^4}$$

A : Surface Area

T : Object Temperatur

Real Calculation of heat Transfer by

- View Factors
- Distance
- Angle
- Temperature Difference
- Surface Emmissivity (for infrared)
 - Transparence possible
- Reflectance (solar)
 - Transparence-> Absorbtiance (solar)

Latitude0degrees

Longitude0degrees

Altitude0m

Model North0

☐ None ☐ User Set ☒ Calculated

Step 1: Specify weather conditions and range of times.
Step 2: Select required time.

Date MM/DD	Time	Azimuth Degree	Elevation Degree	Direct Solar Irradiance W/m^2
Start Date01/01/2010 End Date31/12/2010 Start Time09:00:00 End Time09:00:00				


Direct Solar Irradiance
Calculator
External

Y

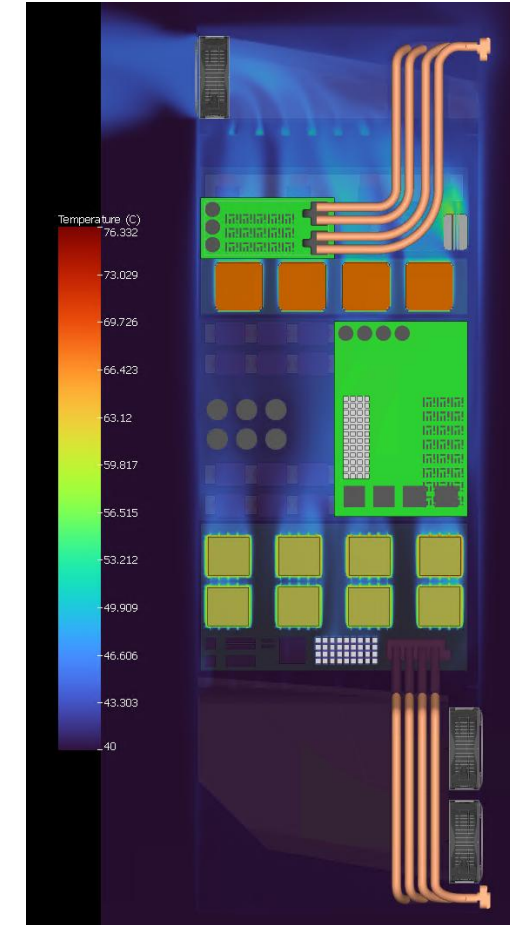
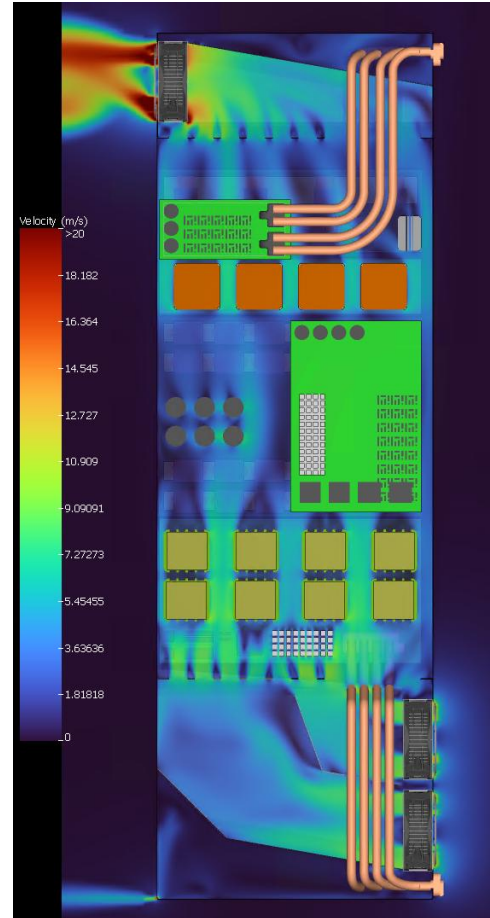
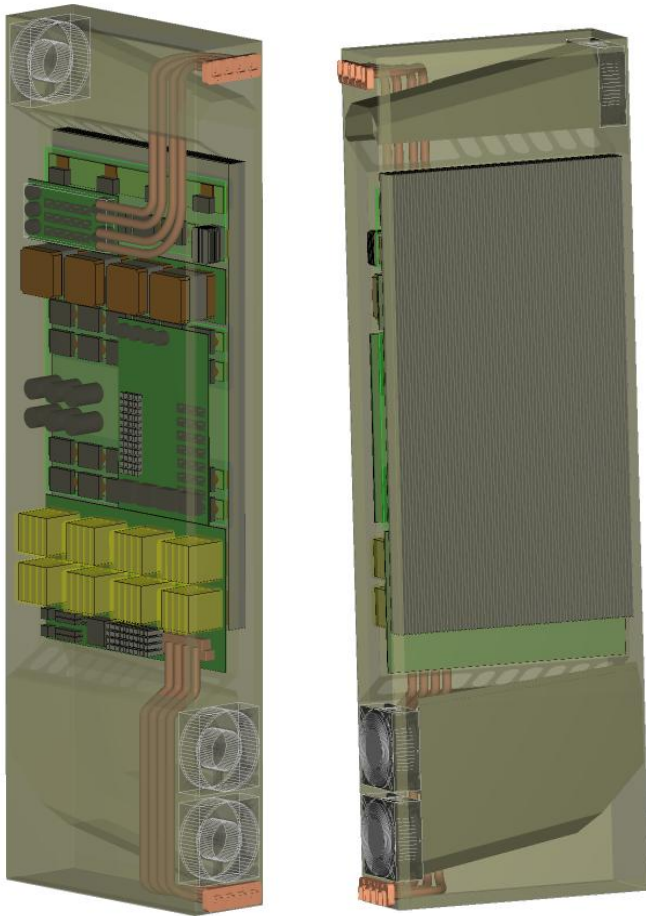
X

Z

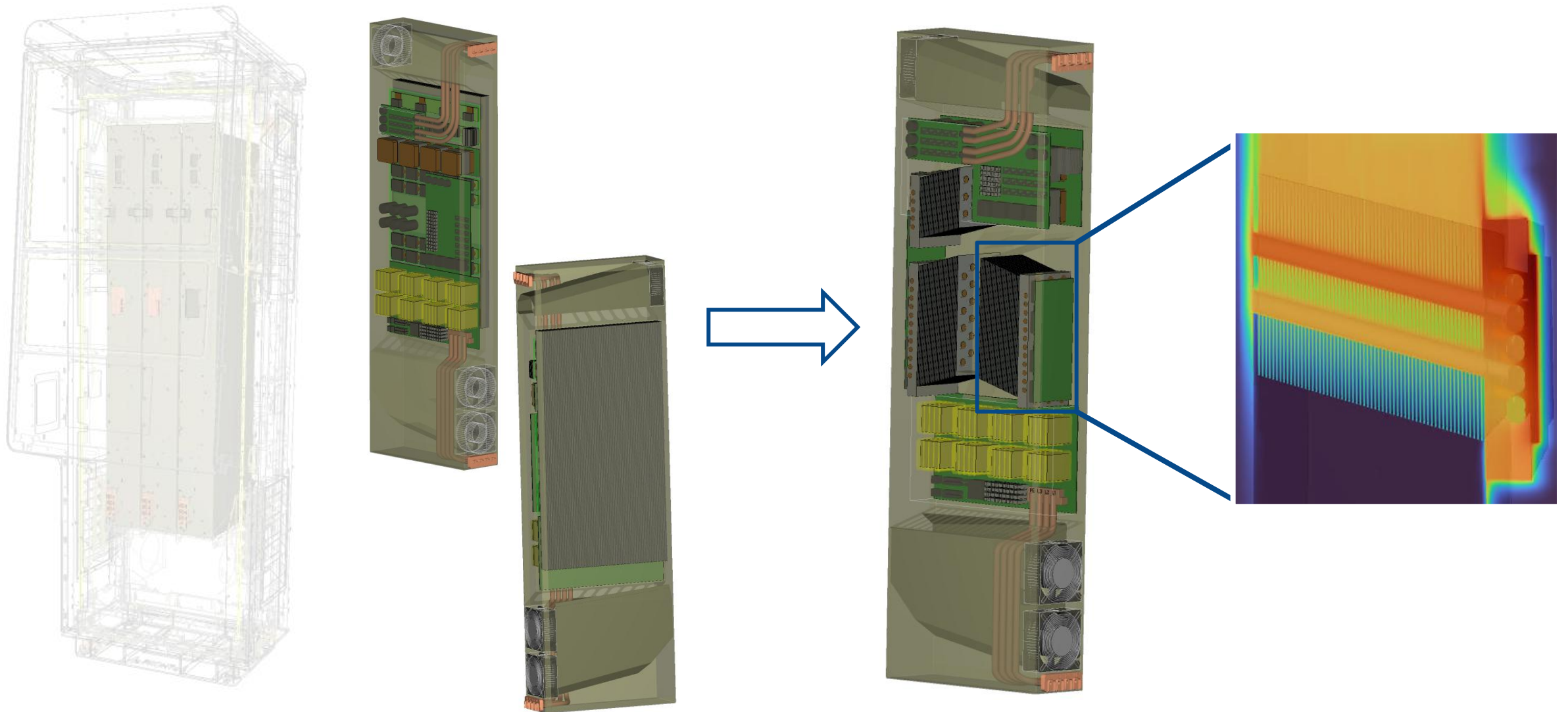
S

The Solar direction is shown by the yellow arrow in the preview

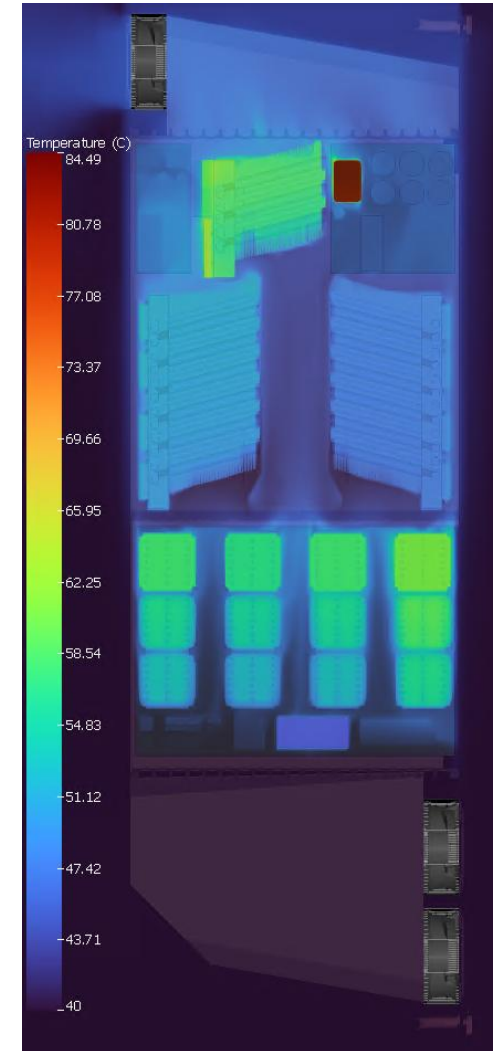
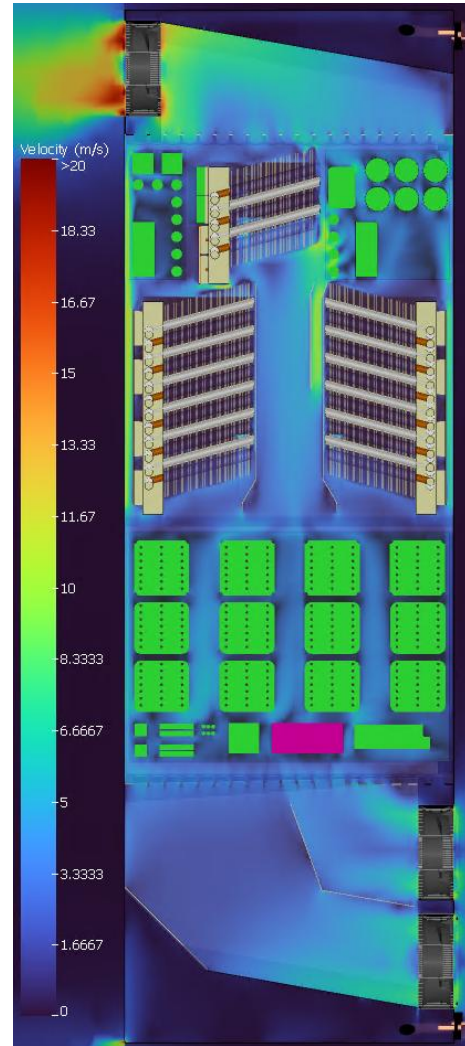
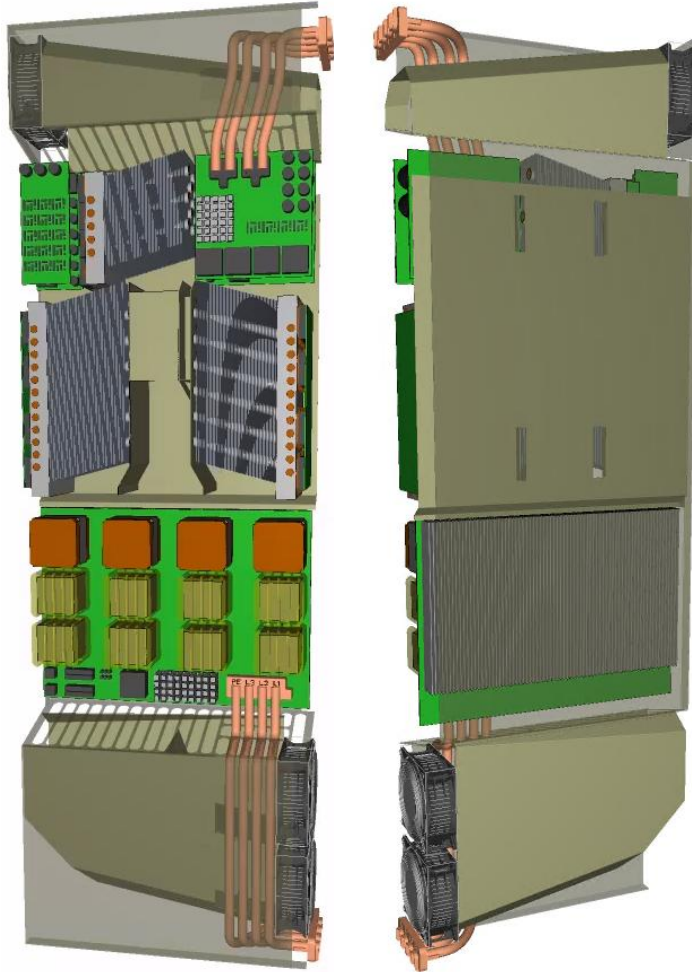
Results at this level will lead into most important design decisions for your cooling strategy



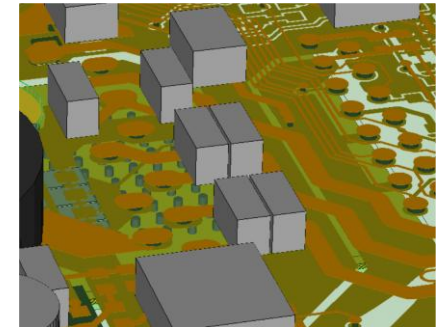
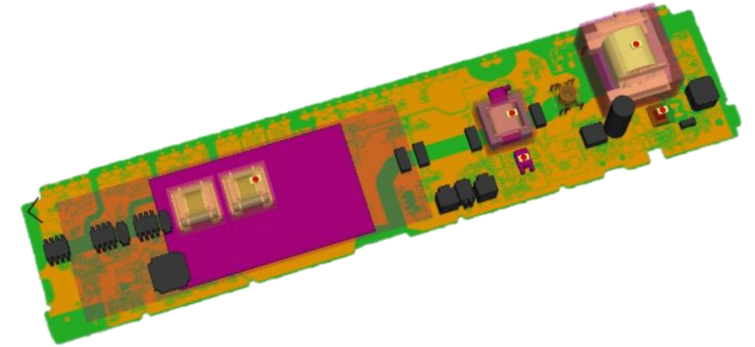
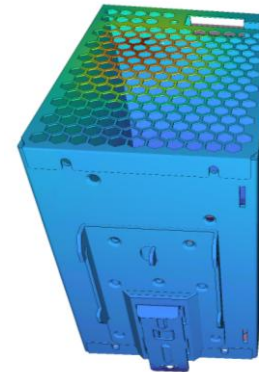
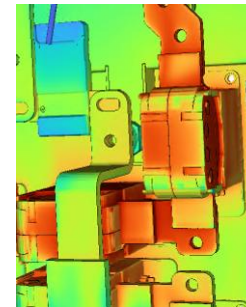
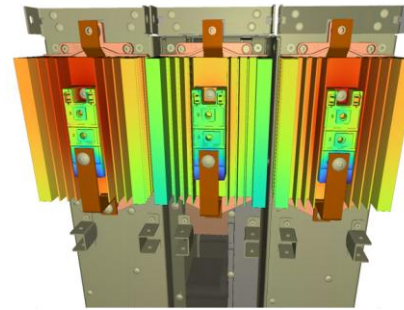
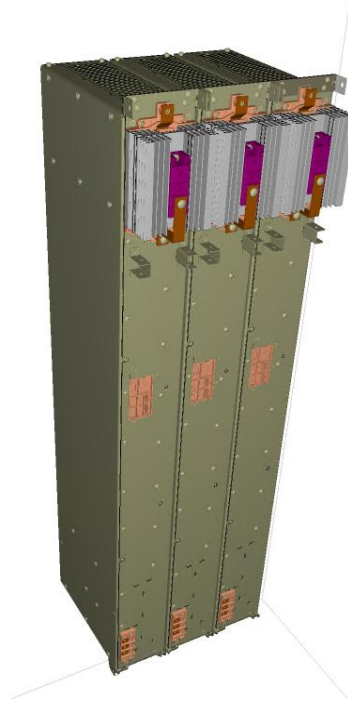
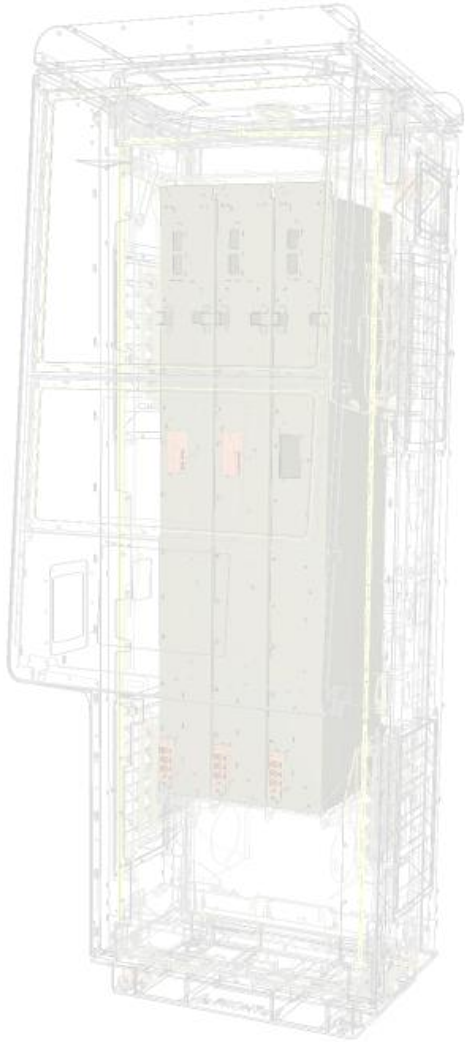
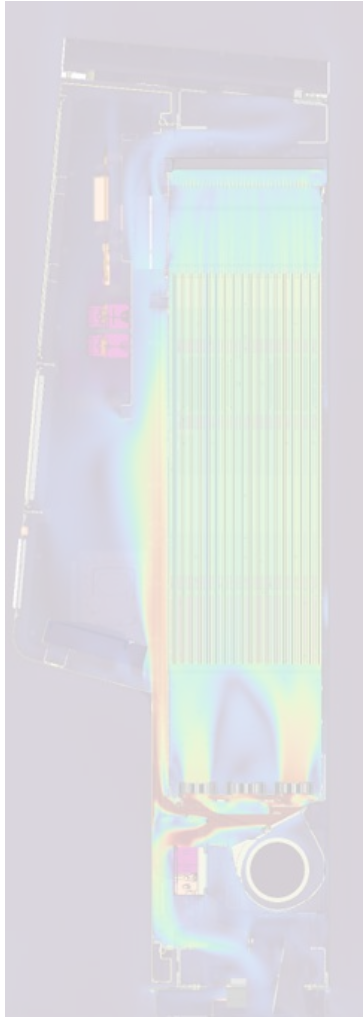
Optimisation at concept level and lift the model to engineering level



Understand the bottle necks and beat the limits



Engineering level will end into a detailed „Digital Twin“



intel_galileo_board.zip

- ext

fonts

input

matrix

misc

output

stackups

steps

symbols

user

wheels

whltemps
- eda

layers

netlists

.attrlist.sum

.profile.sum

.stephdr.sum

attrlist

profile

stephdr

stephdr.sum

☒ Vias

☒ Simplified

☒ Import Non Plated Vias

☐ Ignore Fill Material

☐ Group Identical Vias

☐ Keepouts

☒ Traces

☐ Simplified - Recommend for most thermal mode

☒ Detailed - Increase simulation complexity. Modify

Advanced Options

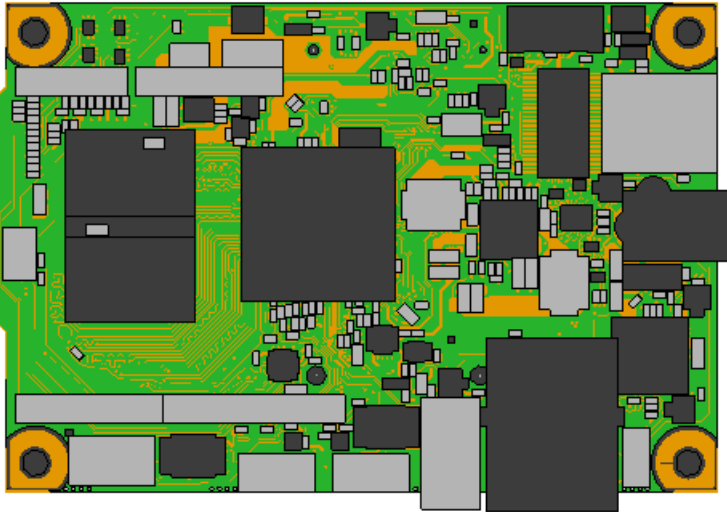
Simplify Shapes☒

Reset Board Origin☒

Ignore holes less than a specified size☐

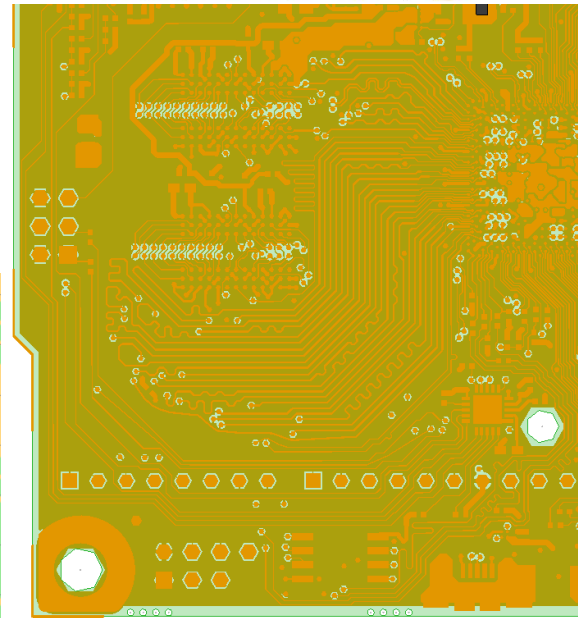
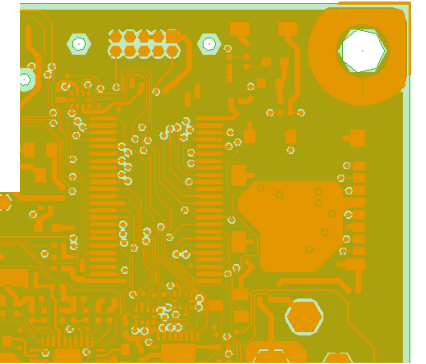
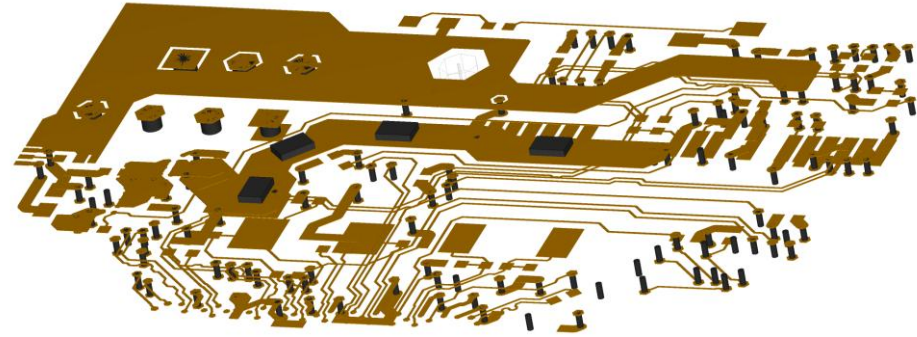
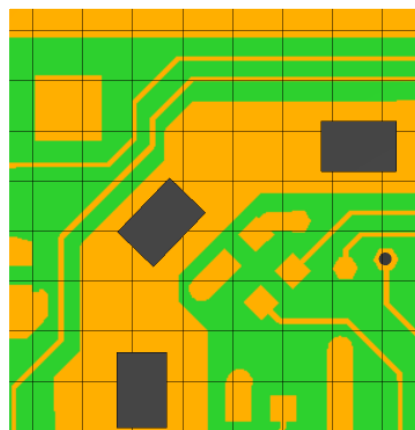
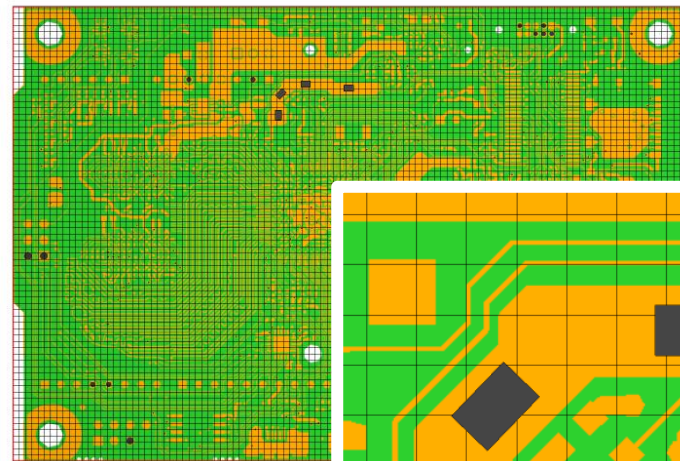
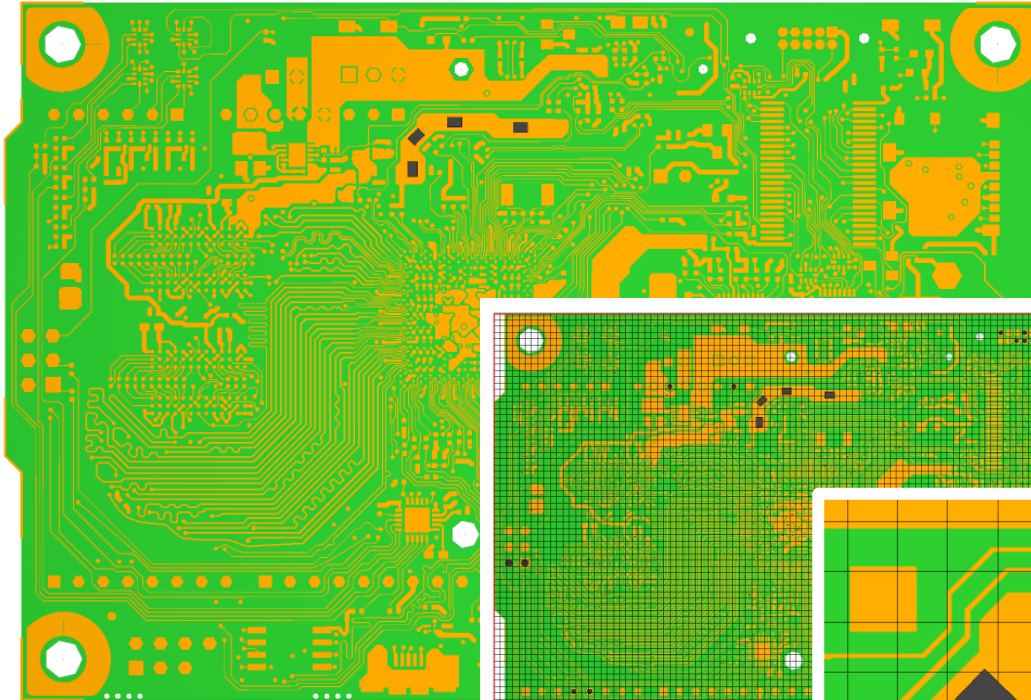
Preview

Type	Count	Filter
Component	75	4
Resistor	240	0
Capacitor	206	0
Daughter Board Socket	14	0
Cable Socket	0	0
Via	2076	0
Traces	2366	0



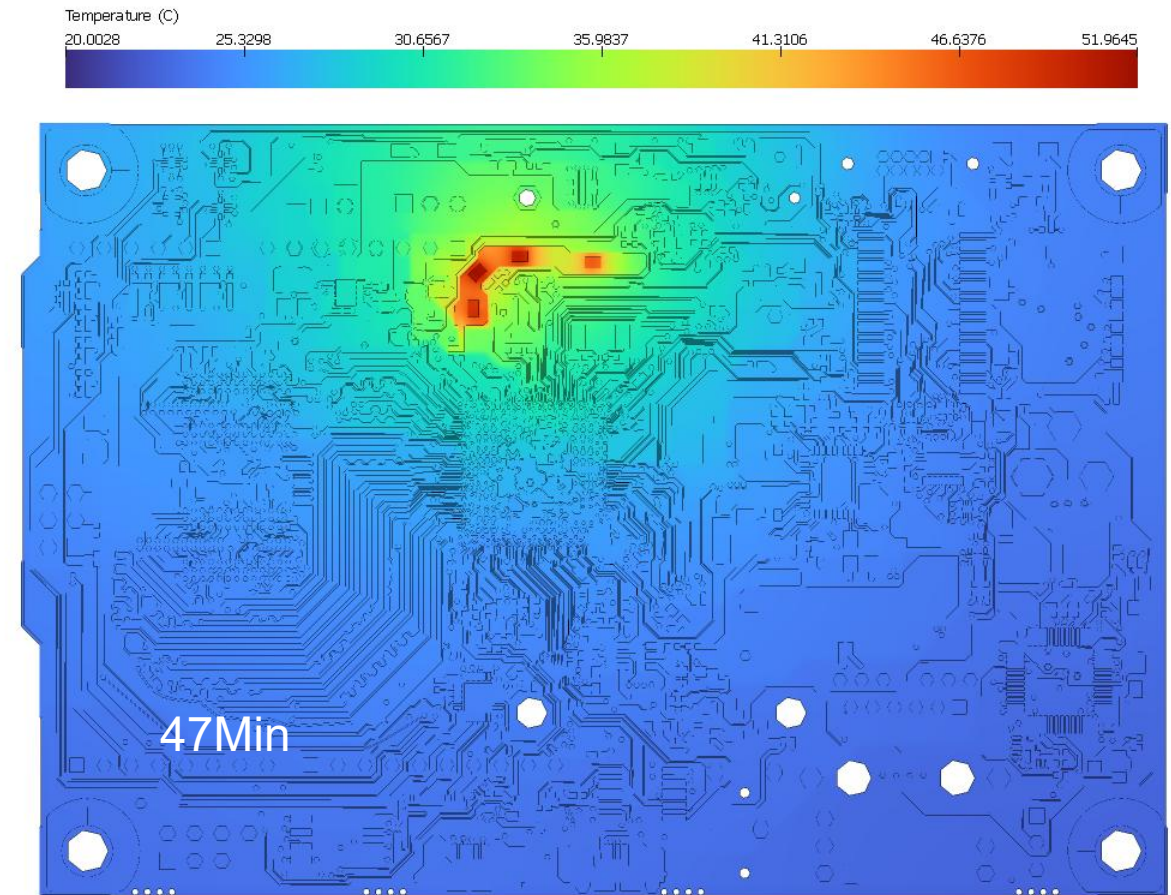
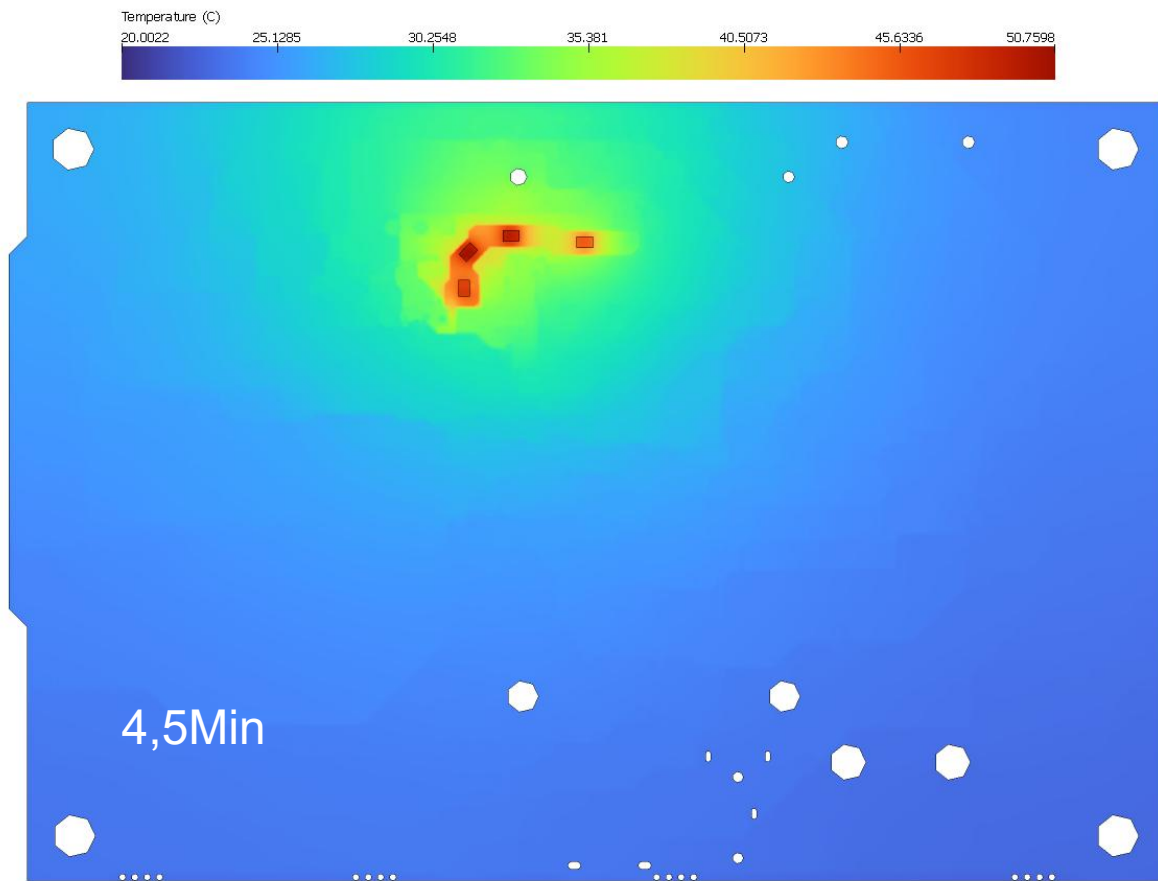
The task will define the level of details you use for simulation

2 395 383 Cells (0 % to 100 % copper)



13 406 085 Cells (0 % **or** 100 % Copper)

Full CFD Calculation with Heat Radiation solved on GPU



Application: High-Power-PCBs – efficient modelling can save a lot of time

Construction

Show Connector ☐

Conductor Material Copper, Pure

Dielectric Material FR4

Modelling Level Explicit Layers

Distribute Layers By Centre

Conductor Layer Quantity 4

Construction Summary

Normal Conductivity 0.3628 W/(m K)

Planar Conductivity 9.5142 W/(m K)

Total Conductor Thickness 0.2798 mm

Calculated Weight 21.95 g

Total Weight 56.69 g

stp (PCB)

Layers

- top
- 2inn
- 3inn
- bottom

Nets

- \$NONE\$
- N328407
- OUT_W
- OUT_V
- EN_W

Conductor Thickness 0.0699 mm

Modelling Level Mixed

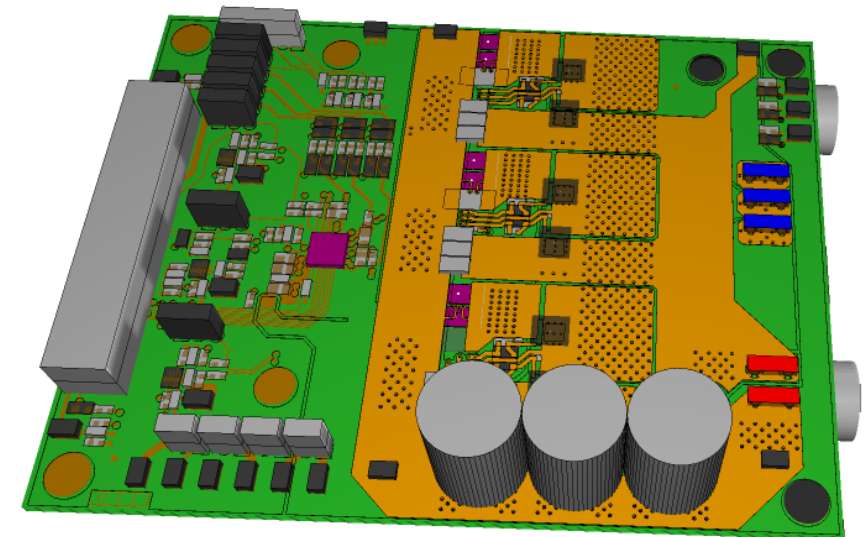
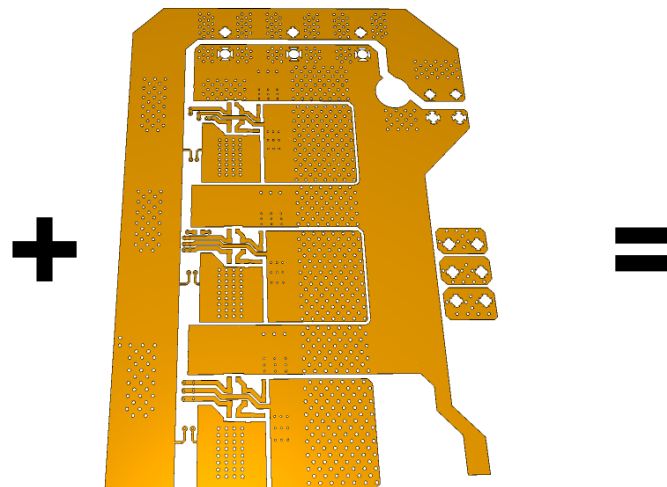
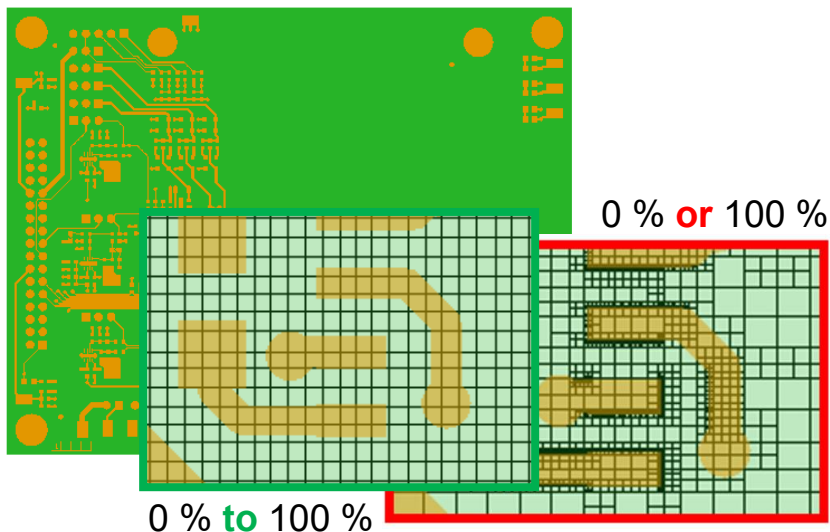
Layer Image C:/Users/Tobias/Docu...

Map Image To Grid ☒

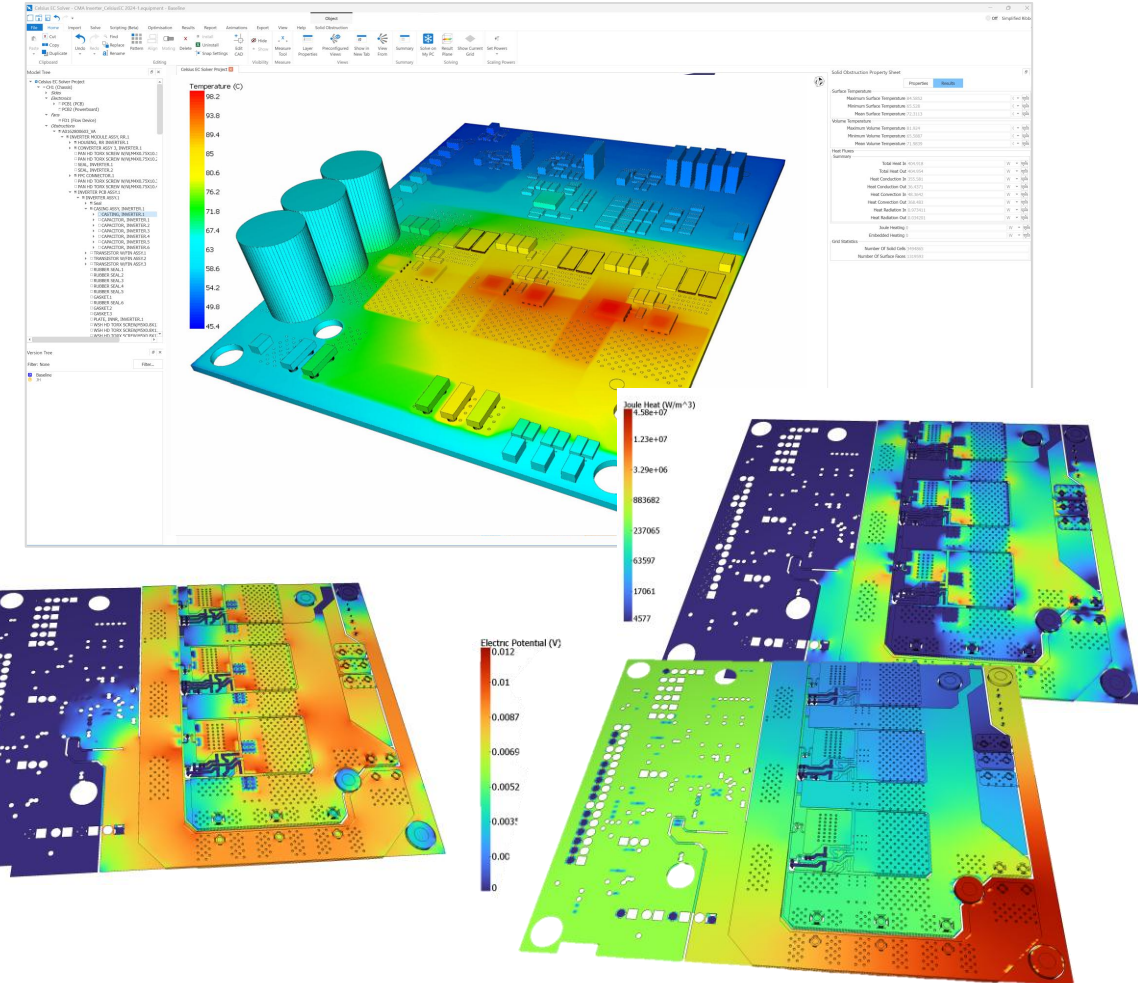
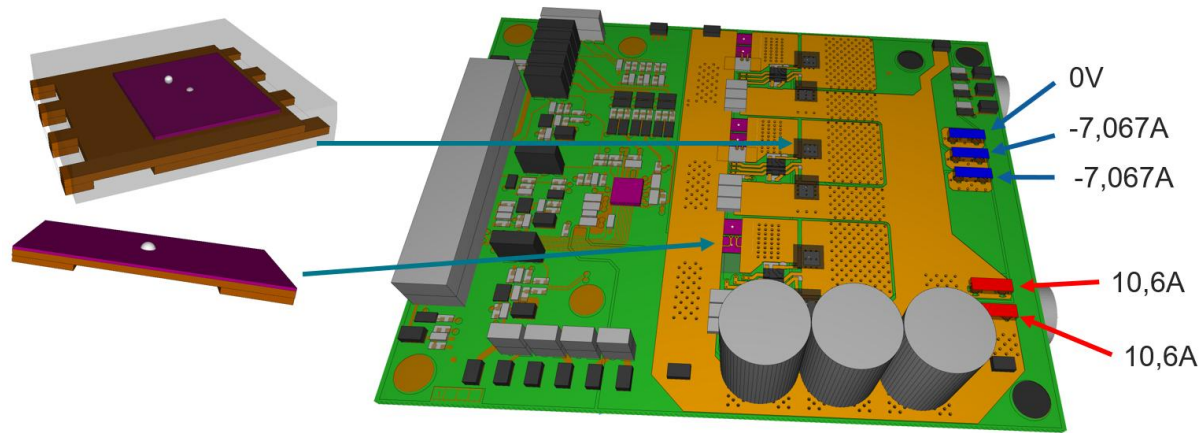
Conductor Percentage From Image 10.59 %

Different Conductor Material ☐

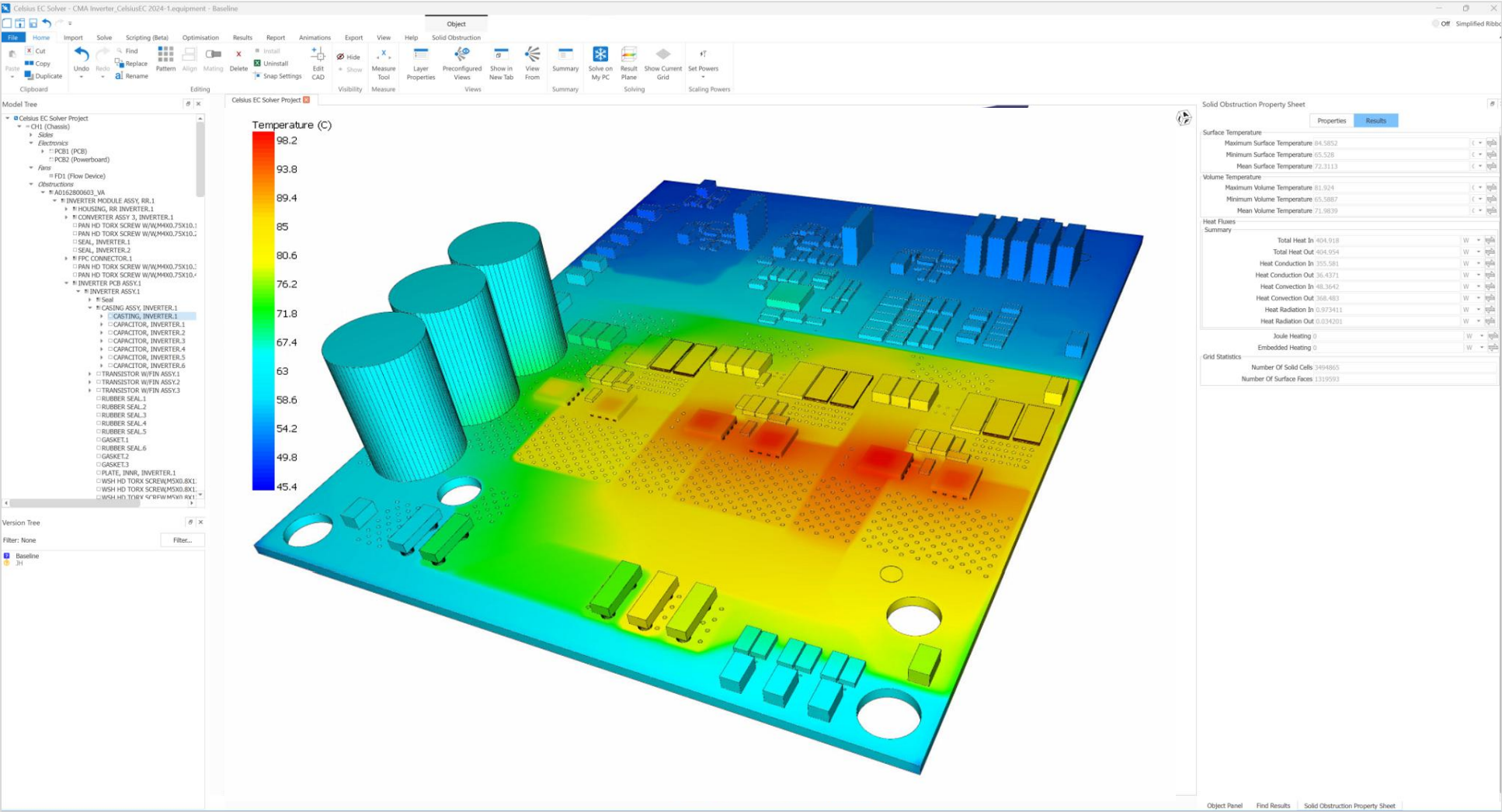
Different Dielectric Material ☐

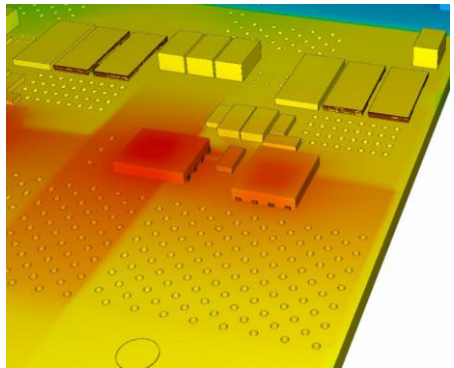
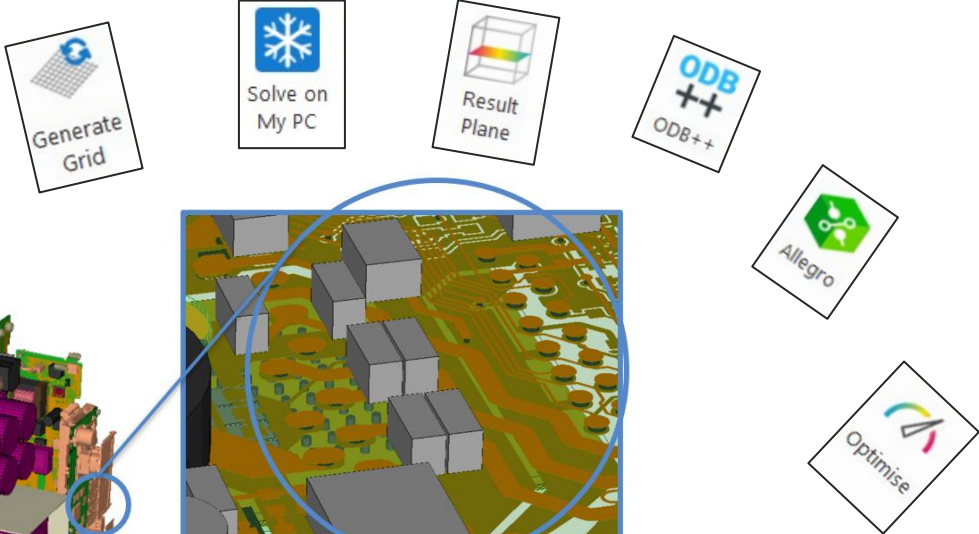
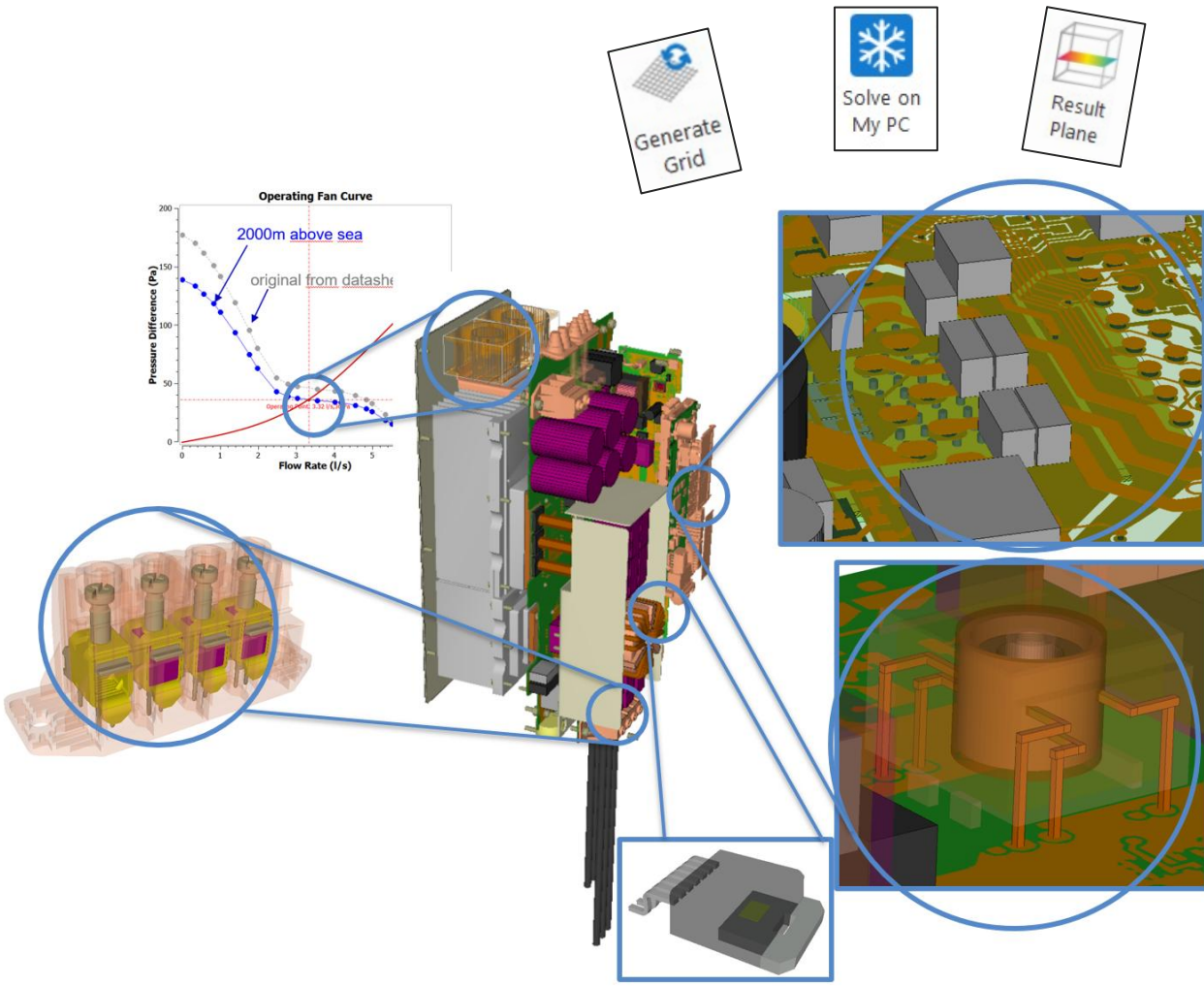
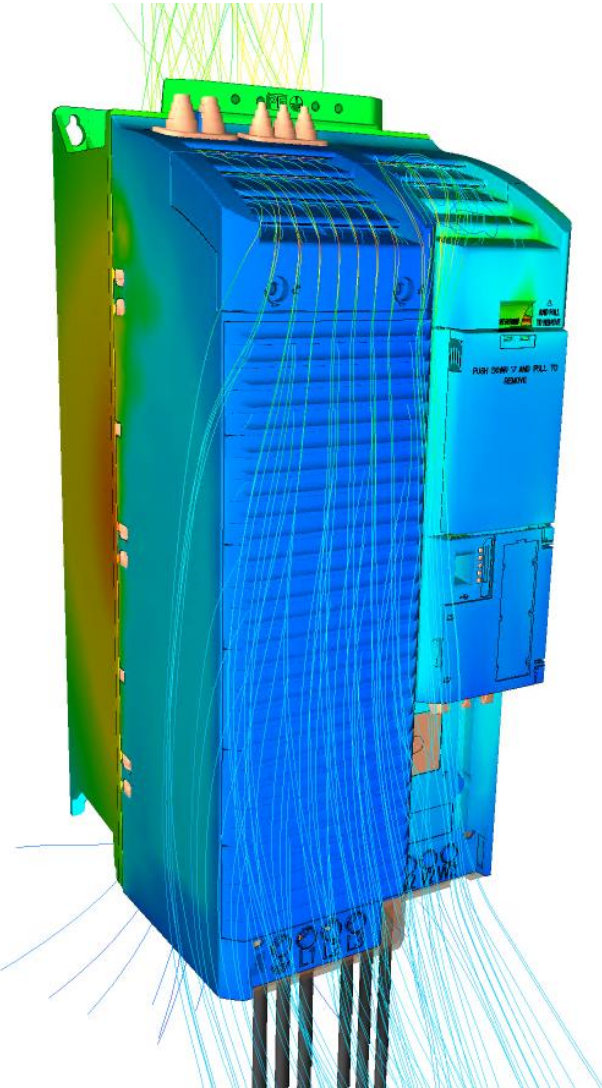


Thermo-Electrical Calculation (Joule Heating in Metal Objects)

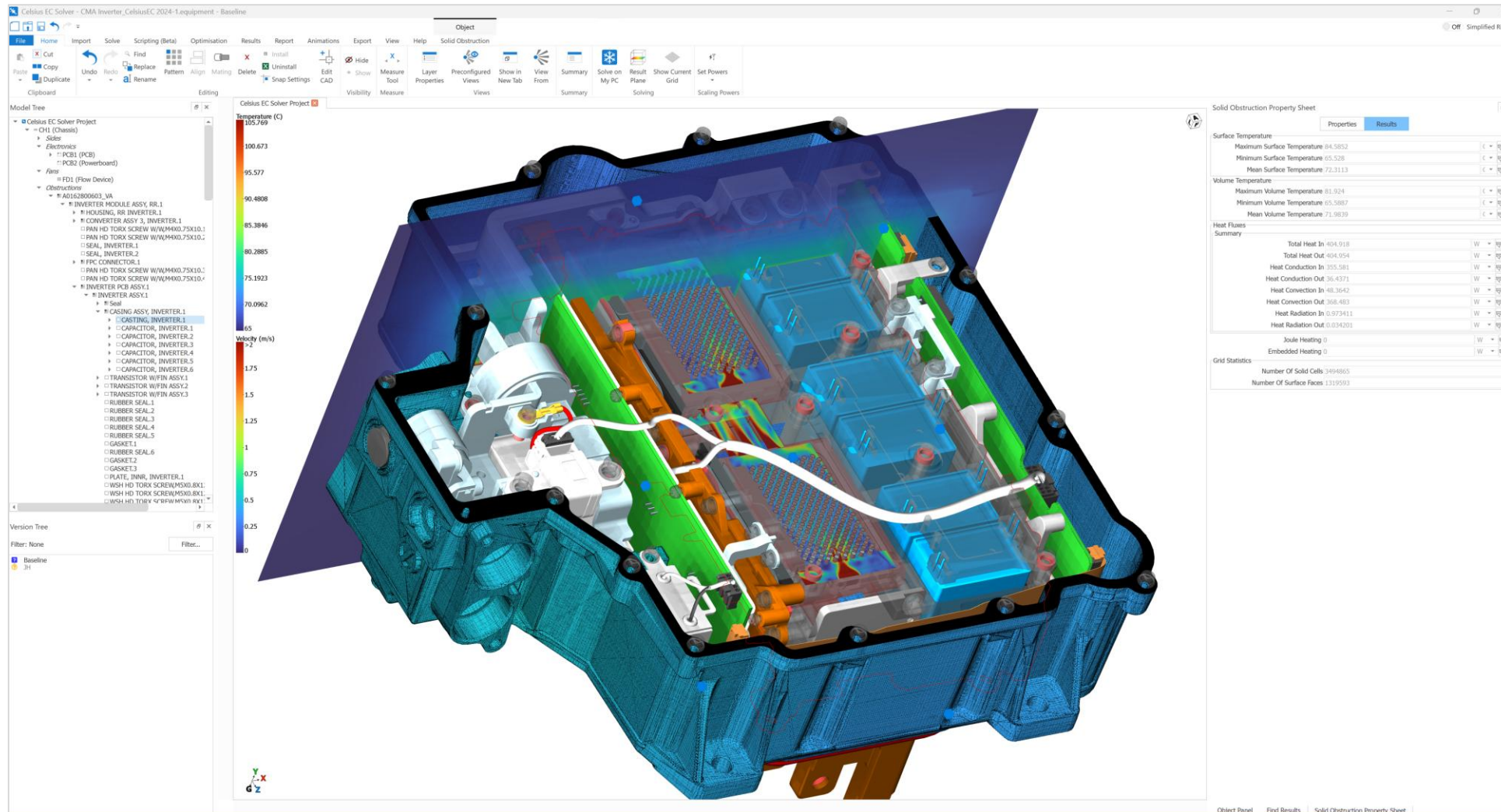


- Temperature and/or time dependant attributes
- Power (W)
- Electrical Sources
- Thermal & Electrical Resistance





Quick Live Demo – Part 3



Thank you for your time



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